# Sentaurus TCAD Training for CMOS Application





#### **Course Outline**

- Sentaurus TCAD Overview
- Sentaurus Workbench
- Sentaurus Process 1D & 2D
- Tecplot SV
- Sentaurus Structure Editor Building Meshes
- Sentaurus Device I-V simulation
- Inspect



#### **Course Outline**

- 90nm nMOSFET Exercise
- C-V Device Simulation
- Breakdown Device Simulation
- pMOSFET Device Simulation
- Ligament introduction
- SolvNet Resources
  - SolvNet Introduction
  - 2D Strained Silicon 45nm CMOS Reference Flow Demo
  - 3D nMOSFET Demo



#### **Synopsys TCAD Overview**







# **Sentaurus Product Family**



- Flexible Framework Environment
   Advanced Visualization
- 2D/3D Process Simulation
  - Calibration Library
  - Structure Editor Interface
- 2D/3D Device Simulation
   Structure Editor and Mesher
   Application Specific Options
  - Application Specific Options
- Process Compact Models
  - Based on Calibrated Flow
  - Links Process Variation and Device Performance

#### Integrated TCAD Flow from Development to Manufacturing



#### Framework

- Provides a GUI-based simulation environment
- Organizes simulation projects, runs and results
- Allows large Design of Experiment (DOE) and statistical analysis
- Manages job scheduling & network computing
- Enables interactive visualization and analysis of simulation results

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#### **TCAD Product Architecture**





#### **Process Simulation**

- Models wafer fabrication steps
  - Implantation, diffusion, oxidation & lithography models are calibrated and highly predictive
  - Etching and deposition are typically modeled geometrically
- Starts from flow description and layout

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#### **TCAD** process flow editor



#### 90nm nFET



#### **Structure Editor**





#### **Device Simulation**

- Models the electrical, optical, mechanical & magnetic behavior of semiconductor devices
  - Simulation is typically performed on structures created by process simulation
  - Modes of simulation
    - Static, time-dependent, large and small signal frequency dependent and noise modeling
- Highly accurate CAD models can be extracted from device simulation results



Simulated current density and flow lines in 100nm device



Simulated electrical characteristics



# **PCM Studio**

- PCM acts as a link between the Yield Management System (YMS) and TCAD
  - PCM from TCAD
  - In-process Metrology and Device Characteristics from Manufacturing
- Graphical & Statistical analysis
- Visualization of experimental data
- Visualization of process-device relations
- Algorithmic analysis
  - Reverse analysis
  - Feed-forward analysis
  - Process Window analysis







# **TCAD Consulting and Engineering**

- Dedicated team of highly proficient engineers with long professional experience
- Close collaboration with the Synopsys software engineers
- Close collaboration with *customers* in consulting and engineering projects
- Service project examples
  - Calibration
  - Process analysis and optimization
  - Difficult simulation types, such as 3D, full-chip, SEU/SER, ESD
  - Customer specific technology templates
  - Customer specific training and know-how transfer
  - Model development and integration
  - Software integration: TCAD FabLink
  - Dedicated engineering projects



10 keV: FLOOP





# Synopsys TCAD

Synopsys TCAD Today Used by 19 out of 20 top semiconductor companies worldwide

Technical and market leadership across all technologies: DSM, Power, Memory, Compound and Optoelectronics

Strong R&D program with research & academia

Dedicated support organization focusing on customer success

Complementary Consulting and Engineering Service Offerings



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#### **Sentaurus Work Bench (SWB)**





#### **Sentaurus Workbench**





#### **Sentaurus Workbench**



Predictable Success

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#### **Overview**

- Sentaurus Workbench is the primary graphical front end that integrates Synopsys simulation programs into one environment.
- Simulations are comprehensively organized into projects.
- Sentaurus Workbench automatically manages the information flow, which includes preprocessing of user input files, parameterizing projects, setting up and executing tool instances, and visualizing results.
- Sentaurus Workbench allows users to define parameters and variables in order to run comprehensive parametric analyses. The resulting data can be used with statistical and spreadsheet software.



# **Starting SWB**

• Before starting Sentaurus Workbench, a database directory to store simulations must be created.

• Users must set the STDB environment variable to point to that directory.

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### **Creating a Project**

- To create a project:
  - Project > New
  - This creates a temporary project with a name similar to g\_lnx\_2879\_0.tmp in the tmp folder that can be viewed in the Projects window
- To set up a tool flow:
  - Right-click the No Tools node under the Family Tree
  - The Add Tool dialog box is displayed

▼ Add Tool	×
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<u>o</u> k	<u>A</u> pply <u>C</u> ancel



#### Editing Tool Command File and Preferences

- Click on the tool icon
- Right click -> Edit Input -> Commands
- To change preferences, Edit Input -> Preferences





## **Running Projects**

- To run a project:
  - Project > Run or Ctrl+R (alternatively, click the Run icon in the toolbar).
  - In the Run Project dialog box, click Run to execute the entire project

\star Run Project/rei	mote/users1/hude/DB/tmp/S 🗙
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# **Viewing Output Results**

- A given node has a number of input and output files associated with it. These can be viewed by right-clicking a node and selecting Visualize. All text and log files can be viewed using SEdit by selecting them.
- All output data files in the case of Dios, Sentaurus Process, Mdraw, Sentaurus Device, and Sentaurus Device EMW can be viewed using Tecplot SV, or a plot of .plx and .plt files in Dios and Sentaurus Device can be viewed using Inspect.
- In addition, the information written to standard output, while a simulation is running, can be viewed by selecting the View Output option.



# **Changing Tree Display Attributes**



- Every simulation node in a project has a color associated with it that indicates its status. The color chart in the lower-right corner of the main window of Sentaurus Workbench shows what each color indicates.
- The format in which the Sentaurus Workbench project tree is displayed is very flexible and user controllable. Users can display solely the tool flow, or can number the various simulation nodes, or can display parameters (splits), variables, extracted values, and other details. To use this feature:
- From the View menu, select or clear the various options, or View
   > Tree Options for more features.



# **SWB** Preprocessing

- As each node is run, SWB prints a message
- Before executing a simulation node, SWB preprocesses the input files.
- Upon preprocessing the files, SWB creates input files of the form pp<node\_number>\_<tool\_na me>.cmd.

Project Log /remote/users1/hude/DB/tmp/SWB_nmos
/remote/users1/hude/DB/tmp/SWB_nmos/glog.txt
queue "local:default" - 40 39 41 42 43 44 45 46 47 48 50 49 51 52 53 54 55 56 57 58 60 59 61 62 10 11 12 13 14 21 22 23 24 25 26 9
<pre>&gt;</pre>
local% submit job 10 for local execution >>>>>>> job '10' status changed from 'ready' to 'pending' local% exec "/remote/tcadprod/bin/gjob -verbose -nice 19 -job 10 "@STDB@/tmp/SWB _rmos""
<pre>&gt;</pre>
<pre>&gt;</pre>
>>>>>>>>>>>>>>>>>>>>>>>>>>>>>>>>>>>>>>
Close



# **Cleaning up Projects**

- To clean up a project:
  - Project > Clean Up.
  - In the Clean Up Options dialog box, select the items to be removed.
  - Click OK.





# **Adding Parameters**

- In SWB, parameters can be defined and multiple values can be assigned to them to create splits in experiments.
- To create each parameter:
  - Right-click the gray box immediately below the Sentaurus Process icon in the main window of Sentaurus Workbench and select Add.
  - In the Add Parameter dialog box, enter the parameter name and default value.

\star Add Param	eter
Parameter:	Туре
Default Value:	nMOS
<u>о</u> к	Cancel



# **Adding Parameters**

- Next, insert the parameters into the input file of the tool:
  - Right-click the tool icon and select Edit Input > Commands.
  - Insert the parameter as @Type@ where appropriate.
- To preprocess the project:
  - Project > Preprocess or Ctrl+P, and view the values.

```
Preprocessor Log /remote/users1/hude/DB/tmp/SWB_nmos_example
                  /remote/users1/hude/DB/tmp/SWB nmos example/gpp.log
n9: parsing 'sprocess lig.cmd' into 'pp9 lig.cmd'
sprocess lig.cmd,4: replace @node@ with '9'
sprocess lig.cmd, 11: replace @<lgate/2.0+0.4>@ with '0.49'
sprocess lig.cmd, 73: replace @<0.5*lgate/-0.04>@ with '-2.25'
sprocess lig.cmd, 73: replace @<0.5*lgate+0.03>@ with '0.12'
sprocess lig.cmd,85: replace @<HaloDose/4.0>@ with '250000000000.0'
sprocess lig.cmd,85: replace @HaloEnergy@ with '15'
sprocess lig.cmd,87: replace @<HaloDose/4.0>@ with '250000000000.0'
sprocess lig.cmd, 87: replace @HaloEnergy@ with '15'
sprocess liq.cmd, 89: replace @<HaloDose/4.0>@ with '250000000000.0'
sprocess lig.cmd,89: replace @HaloEnergy@ with '15'
sprocess lig.cmd, 91: replace @<HaloDose/4.0>@ with '250000000000.0'
sprocess lig.cmd,91: replace @HaloEnergy@ with '15'
sprocess_lig.cmd,108: replace @<0.5*lgate=0.04>@ with '0.05'
sprocess lig.cmd,141: replace GnodeG with '9'
sprocess lig.cmd, 153: replace @<0.5*lgate+0.39>@ with '0.48'
sprocess lig.cmd, 155: #set Lgeff 'x'
sprocess liq.cmd,157: #set Xj 'x'
sprocess lig.cmd,159: #set Yqox 'x'
sprocess lig.cmd, 161: #set Tox 'x'
n9: parsing 'sprocess' ligament command
ligament: replace @tool@ with 'sprocess'
n9: run /remote/tcadprod/bin/ligament -simulator sprocess -flow pp9 lig cmd -l
ayout sprocess lig.lyt -contact sprocess lig.con -layoutcmd pp9 lig.lcf sproces
s lig.cmd n9'
> TARGET sprocess
> Done
% updating the SWB variables from ligament
n9: parsing 'sprocess' cmd line
n0. and line - "-u -h n0 fre and"
                                        Close
```



# Adding New Experiments (Rows)

- To create multiple experiments:
  - Experiments > Add New Experiment.
  - Enter the values for parameters
- Or right-click the parameter name and select Add Values

✓ Add New	Experiment	×	✓ Add Parameter Values
Scenario:	all	•	Scenario: all 💌
			Parameter: Igate 💌
Туре:	nMOS	•	·
Igate:	0.18	•	Min. Value: 0.18
HaloDose:	1e13	•	Step: 1
HaloEnergy:	15	•	Number of Values: 1
PolyDop:	6e19	•	🔶 Lin 💠 Log
Vdd:	1.5	•	Format:
Vds:	1.5	•	Add values to selected experiments only
<u></u> K	<u>Apply</u> <u>Cancel</u>		<u>OK</u> <u>Apply</u> <u>Cancel</u>



# **Using Scenarios**

- Scenarios are sets of experiments (rows)
- Creation of different scenarios is particularly helpful when many parameters are used
- Experiments can be classified into separate scenarios to represent different physical situations.
- You can display different scenarios in the main window of Sentaurus Workbench by scrolling through the Scenario menu (black border) in the toolbar

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# **Pruning the Tree**

- Often, when many parameters are used in a project, certain combinations of parameters are not required to be simulated.
- In such cases, the project tree can be pruned by terminating such experiments.
- For example, assume that in the scenario New1 the experiments for Igate=0.18, HaloDose=1e13, HaloEnergy=25, and Vds=0.05 are not required to be simulated.
- Therefore, the project can be pruned at node 41 as follows:
  - Select node 41.
  - Node > Prune.
  - Nodes 41 and 53 are pruned and appear gray.



#### Variables vs. Parameters

- If a certain parameter is going to change only for certain experiments, a variable could be used instead.
- To add a variable:
  - Variables > Add.
  - Enter Vsub in the Variable field with a default value of 0.0.
- This sets the substrate bias to 0.0 as before. The same could have been performed by defining a parameter called Vsub.
- Now assume you want to set the substrate bias to -1.0 V only for experiment 3, (node 41), retaining 0.0 V for all other experiments.
- Edit tool command file for node 41:
  - { Name="substrate" Voltage=@Vsub@ }
- Right-click node 41 ([n41]) and select Set Variable Value. In the dialog box, select Vsub and set the value to -1.0 V.
- Now, preprocess the project. After it is completed, view pp41\_des.cmd. @Vsub@ is replaced by -1.0 V.



# **Exporting Scenarios and Experiments**

- Scenarios, that is, sets of parameters and variables visible in the SWB main window, can be exported to a file either for use with a spreadsheet application or an external editor.
  - View > Export.
  - In the Export View dialog box, select Tab for the Column Delimiter.
  - Click OK.
  - In the Save As dialog box, select Tab delimited (\*.tdf) for Files of type and provide a file name (for example) test.tdf. This exports the scenario to a file.

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	Include Col	umn Names
Col	umn Delimit	er:
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$\diamond$	Space 💊	Semicolor
Ŷ	Other:	
	ок	Cancel



# **Importing Experiments**

- Experiments > Import from a File and select the file test.tdf.
- To create a scenario in an external text editor and import it into SWB, create a table, and save it in comma-delimited or tabdelimited format.

	Standard	Standard	Standard	Standard	Standard	\$
1	Туре	lgate	HaloDose	HaloEnergy	PolyDop	V
2	nMOS	0.14	5.00E+12	13	5.00E+19	1
3	nMOS	0.12	6.00E+12	14	6.00E+19	1

Y	Import Experiments
Г	-Scenario
	Add to Scenario: test
-	
Γ	-Parameters
	Type: <ul> <li>Column:</li> <li>Q</li> <li>Value:</li> <li>MOS</li> <li>A</li> </ul>
	Igate: 🔶 Column: 1 🚔 💠 Value: 0.18
	HaloDose: 🔶 Column: 2 🚔 🔷 Value: 1e13 🔹
	HaloEnerov: I Column: 3 A Value: 15
-	
Г	- Format
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	Skip First 0 🚔 Lines. Read 13 🚔 Experiments.
	Treat Consecutive Delimiters As One
Γ	-Preview of /remote/users1/hude/DB/tmp/test.tdf
	Type lgate Balobose Balobnergy PolyDop Vdd Vds n#DS 0.18 1e13 15 6e19 1.5 0.05
	nHUS         0,18         1e13         15         6e19         1.5         1.5           nHUS         0,18         1a13         25         5a19         1.5         0.05
_	
	<u>O</u> K <u>P</u> review <u>C</u> ancel

Predictable Success

# **Attaching Project Directories**

- In addition to displaying the projects within the \$STDB directory, projects located elsewhere can be attached to the displayed list:
  - From the Edit menu, select Attach Root
  - Select the required project directory
- This procedure can be repeated to attach up to <u>five</u> project directories.
- To remove a project directory:
  - Select the required project directory.
  - Edit > Detach Root.
- Only attached roots can be detached. The projects in the \$STDB environment cannot be detached, but they can be deleted permanently.



### **Copying Sentaurus Workbench Projects**

- To run a project, copy the project from the Examples Library:
  - Open the Examples Library > Getting Started, and select the project SWB\_nmos.
  - Right-click and select Copy.
  - Select the tmp folder, right-click, and select Paste to place the project in tmp.
  - Open the tmp folder and double-click the project SWB\_nmos.

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		(n3): 0.18	[n5]: 1e13		1				b411-0.05	InS31	0.348	0.324
				[n10]: 25	[n16]:	[n22]: 6e19	(n28) (r	[n34]: 1.5	In421-1.5	In541	×	0.294
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				fuiel-in	lurol				[n46] 1.5	[n58]	ж	0.230
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		-			_							-


# **Archiving Projects**

- Sentaurus Workbench projects can be archived, that is, they can be copied and compressed for later use.
- To archive a project: Project > Export (tar).
- All the files in the project directory are copied and compressed.
- To import archived projects: Project > Import (tar).
- In addition, projects can also be saved using Project > Save Clean As, which cleans up the project before it is saved in an uncompressed format.



# **Online Manuals and Training Material**



#### **Sentaurus Process (SProcess)**





# Outline

- Sentaurus TCAD coordinate systems
- Script file setup sequence
- 1D example
- 2D example
- Implement external variable on Sentaurus Workbench



# Sentaurus TCAD Coordinate Systems (default setting)

SProcess

Tecplot, SDE, SDevice





# **Script File Setup Sequence**

- Setup initial mesh
- Define initial simulation domain
- Initialize simulation & define substrate condition
- Setup process flow
  - Oxidation / Deposition / Etching / Implantation / Annealing
  - Rebuild mesh at appropriate steps
- Define electrodes
- Save full structure
- Extract parameters



# Ligament commands





#### Limitation of basic Ligament Flow Editor command

The below table is comparison of supported features.

Support feature	Non-support feature
by basic command	by basic command
<ul> <li>Anneal (Oxidation, Diffusion)</li> <li>Anisotropic and Isotropic Etch</li> <li>Anisotropic and Isotropic Depo</li> <li>Epi</li> <li>Pattern(mask)</li> <li>Implant</li> </ul>	<ul> <li>Trapezoidal and Polygon etch</li> <li>Fill</li> <li>Mesh strategy</li> <li>Extraction of parameter</li> <li>Changing models</li> <li></li> </ul>

Complicated feature is not supported by basic command.



# Insert command

- These special commands can be specified by insert command.
- These operation is used to insert original commands of Sentaurus Process directly.

#### **Basic rule**

 $\rightarrow$ 

There are characters, \$, ", [, ] and \.

\ is necessary to be placed just before these characters like below: **Examp**<sup>1</sup>2<sup>1</sup>

Original command
refinebox name=emitter \
min= {0 0} max= {1 0} \
xrefine= {0.1} yrefine= {0.1}

→Error!

Modified command
refinebox name=emitter \\
min= {0 0} max= {1 0} \\
xrefine= {0.1} yrefine= {0.1}



#### Basic command rule of Sentaurus Process (1/2)

 Long commands can be separated into several lines by ending each line with a backslash \.

#### Example:

etch Silicon type=polygon \ polygon= { 0.0 0.5 1.0 0.6 \ 1.0 2.4 0.0 2.5 \ }

If there is combination, = {value}. The command should be:
 Example:

refinebox name=emitter min= $\{0 \ 0\}$  max= $\{1 \ 0\}$  xrefine= $\{0.1\}$  yrefine= $\{0.1\}$ 

#### → Error!



# Basic command rule of Sentaurus Process (2/2)

If there is combination, value<unit>. Ex) 50<nm>
 User should not insert space between value and <unit>



• Sentaurus Process supports "TCL script" command. Please refer to a reference book or web if you want to know the detail.



#### **Taper etching**





# Taper etching

- Etch command supports basic feature
  - > Isotropic
  - > Anisotropic.
- Taper etching.  $\rightarrow$  Simulator-specific command is necessary.
- Performs a trapezoidal etching.  $\rightarrow$  Define the thickness and angle parameters.

#### An examples is:

etch material=PolySilicon type=trapezoidal thickness=0.55 (angle=8

-0.6

-0.4

0.2-

0.2



Predictable Succes

# **Ex: taper etching**

- Copy the project "/PostBasic/question/sprocess/base" under STDB folder.
- Change copied project's name to "taper\_etch".
- **3.** Open the project and start Ligament Layout Editor.
- 4. Delete the first <u>etch</u> command for Poly.







# Ex: taper etching (cont.)



etch material=PolySilicon type=trapezoidal thickness=0.55 angle=85

# 8. If you have time, please try other angles.



### Ex: taper etching ~the result~





# Appendix ~polygon etch~

- Complex figure
  - $\rightarrow$  Use polygon etch to specify coordinates.





### **Definition of mesh**





# Mesh Overview (1/2)

- Mesh is important : Accuracy are dependent on the mesh
- Surplus dens-mesh.
   → Long calculation time.
- To improve calculation time, dense mesh is placed at :
  - ➤ strict profile
  - strict geometry



Combination improves the perfo Synopsys<sup>®</sup> Predictable Success

# Mesh Overview (2/2)

 The mesh command is inserted before the implantation or oxidation... process step
 → This is effective to reduce calculation time.

- User have to decide mesh strategy.
- There are three types of mesh:
  - ► line :

Initial mesh defined at first.

➤ mgoals :

Additional mesh for the interface at etching and deposition

➤ refinebox :

Additional mesh for change of strict profile and geometry by oxidation.



### Mesh Type ~line~

- This is used only for initial mesh (grid) size.
- Mesh size is changed after "mgoals" and "refinebox".





# Mesh type ~mgoals~ (1/2)

- mgoals means "Mesh and Geometry OperAtions using the Level Set method".
- deposition and etching

   → the geometry is changed
   →Automatically works
   along the interface
- The right example shows after deposition and etching.





# Mesh type ~mgoals~ (2/2)

• User need to specify the parameter.

The parameters (mesh size) of "mgoals" are important for calculation of diffusion profile near the interface.

- It works on the interface of Si, Poly-Si and SiO<sub>2</sub> by default.
- The below statement "grid remesh" forces an "mgoals" remeshing step.
   grid remesh

 "grid remesh" is recommended after an oxidation step because "mgoals" does not work oxidation step automatically.



# Mesh type ~refinebox~ (1/2)

- refinebox works at the specified local area ("mgoals" works only the interface.)
- Explicitly specify the coordinate of area.

• Generally strict profile is appropriate area for refinebox, see the right figure.





# Mesh type ~refinebox~ (2/2)

 Strict boundary by oxidation is also appropriate area for refinebox.





# Mesh command : mgoals ~usage~ (1/2)

```
mgoals min.normal.size=5<nm> max.lateral.size=2.0<um> \
    normal.growth.ratio=2.0
```

pdbSet Grid Mgoals UseLines 1

#### **Command option**

- **min.normal.size** : The smallest normal (to the interface) mesh element size on either side of an interface. The default value is 1nm.
- normal.growth.ratio : Used to increase the normal size of the element, moving away from the interface. The default is 2.0.
- max.lateral.size : The maximum lateral (parallel to the interface) spacing between elements. This is, however, also used to define an upper bound on the normal size. The default value is 1um.
   Large Device :

 $\rightarrow$  Larger value of "min.normal.size" and "max.lateral.size" than default might be good. The calculation time might be improved.



# Mesh command : mgoals ~usage~ (1/2)

mgoals min.normal.size=5<nm> max.lateral.size=2.0<um> \
 normal.growth.ratio=2.0

pdbSet Grid Mgoals UseLines 1

 pdbSet Grid Mgoals UseLines 1 : It is recommended to use the UseLines mesher because this produces better element quality and better mesh reproducibility that reduces numeric error due to interpolation.



### Mesh command: mgoals ~parameter~





# Ex: mgoals parameters (1/2)

- **Purpose :** confirm the parameters for "mgoals".
- Copy the project "/PostBasic/question/sprocess/base" under STDB folder.
- 2. Change copied project's name to "mgoals".
- 3.Open the project and start Ligament Flow Editor.
- 4.Insert the "<u>insert</u>" command after #endheader command.

5.Specify mgoals command like below:



mgoals min.normal.size=@MNS@ normal.growth.ratio=@NGR@ pdbSet Grid Mgoals UseLines 1



# Ex: mgoals parameters (2/2)

6. Save and close Ligament Flow Editor.

Then, try two items.

Vary min.normal.size's value : 0.001/0.002/0.005/0.01 with normal.growth.ratio=1.41 Use parameter "MNS" in swb environment.

Vary normal.growth.ratio's value : 1.1/1.41/1.73/2.0 with min.normal.size=0.001 Use parameter "NGR" in swb environment.



# Ex: mgoals ~the results~ (min.normal.size)





# Ex: mgoals ~the results~ (normal.growth.ratio)





# Mesh command : refinebox ~usage~



- \ means that the command continues in next line.
- "grid remesh" is necessary just after "refineb....





# Ex: refinebox (1/3)

- **Purpose :** confirm the effects of refinebox command.
- Copy the project "/PostBasic/question/sprocess/refinebox" under STDB folder.
- 2.Change copied project's name to "refinebox"
- **3**.Open this project and start Ligament Flow Editor.
- 4.Insert <u>#if</u> command before the implant command. After that, if and end commands are added. Then, specify @refine@in #if parameter
  - of if command's argument.







# Ex: refinebox (2/3)

- Insert the <u>insert</u> command between #if command and #endif command.
- 8. Specify refinebox command like below:

```
refinebox name=RB.Top \\
    min= {0 0} max= {0.75 3} \\
    xrefine= {0.07} yrefine= {0.5}
refinebox name=RB.Con \\
    min= {0 0.7} max= {0.5 1.2} \\
    xrefine= {0.05} yrefine= {0.05} \\
refinebox name=RB.Con \\
    min= {0 0.8} max= {0.4 1.0} \\
    xrefine= {0.02} yrefine= {0.02} \\
```

Variables & Macros Flow Unfolded Flow		
Names	Arg	
白····································		
PP #header		
i environment	title	
substrate	dopant	
comment	text	
PP #endheader		
deposit	material	
🛛 📥 deposit	material	
pattern	layer	
etch	material	
etch	material	
inser	dios	
#endif		
implant	species	
anneal	time	
i 🔚 save	basename	

9. Save and close Ligament Flow Editor.



# Ex: refinebox (3/3)

10. "Parameter  $\rightarrow$  Add" in the Sentaurus Workbench main window. The Add Parameter dialog box is displayed.

- 11. Enter refine in the Parameter field and "0" as the Default Value.
- 12.Click OK.

The "refine" parameter is added to the Sent Project Scheduler project.

13.Add value "1" to the refine parameter. An Experiment with "0" is without refinebox. An Experimant with "1" is with refinbox.




#### Ex: refinebox ~The results~





### Ex: refinebox ~ comparison of 1D profile at y=1.0 ~





### Mesh command: refinebox ~Advance~

Mesh size can be gradient by x/yrefine option





#### **Extraction**





#### Extraction

- Sentaurus Process supports the extraction, layer thickness, Xj and so on.
- This feature is useful to check these values.
- Some useful command is introduced from next slide.



# **Extracting oxide thickness**

- Sprocess can extract the interface coordinates.
- User can extract material (layer) thickness.
- An example is :

```
set x1 [interface Oxide /Silicon y=2]
set x2 [interface Gas /Oxide y=2]
puts "DOE: Tox_A [format %.1f [expr ($x1 -$x2)*1000]]"
```

- "interface" is the command for extraction of interface coordinate.
- "puts "DOE..." is for displaying the result on swb.
- "Tox\_A" is variable name for output.
- "format %.1f" is output format of the fractional part of decimal fractions.
- "expr (\$x1 -\$x2)\*1000" is for calculation the difference of each coordinate and convert unit from µm to angstrom.



# Ex: extracting oxide thickness (1/2)

- Purpose : extract oxide thickness
- 1.Copy the project "/PostBasic/question/sproce ss/base" under STDB folder.
- 2.Change copied project's name to "extract\_tox"
- **3.**Open this project and start Ligament Flow Editor.
- 4.Insert <u>insert</u> command the last etch command and define parameters :





# Ex: Extracting oxide thickness (2/2)

5. Specify sprocess-specific command in **insert** command like below:

set x1 \[interface Oxide /Silicon y=2\] set x2 \[interface Gas /Oxide y=2\]

puts \"DOE: Tox\_angstr \[format %.1f \[expr (\ $x1 - \x2$ )\*1000\]\]\"

#### Caution

\ are needed before some special symbolic character, [, ], " and \$ because Ligament cannot recognize special character without \.

6. Finish Ligament Flow Editor and run the project.



### Ex: Extracting oxide thickness ~The result~

• Extracted value is displayed on swb.

Project	Scheduler	
	Family Tree	Variable Values
	Seniaurus P	
	sprocess	
		Tox_angstr
1		100.0



# **Extracting Xj**

 Sprocess can extract xj at the specified location with "interpolate" command.

An example for extraction of Xj is :

```
select z="NetActive"
set x0 [interpolate Silicon y=2 value=0]
set x1 [lindex $x0 0]
set x2 [interface Oxide /Silicon y=2]
puts "DOE: Xj_um [format %.1f [expr ($x1 -$x2)]]"
```

- select command define extraction parameter for value keyword.
   NetActive means "*n*-concentration *p*-concentration"
- y, value: The combination of these parameters determines how the command operates. y and value are given, the locations along y where value is crossed are returned.
- lindex : Return the first value if returned values are multiple.



# Ex: extracting Xj (1/2)

- Examine the following parameters for refinebox
- Copy the project "/PostBasic/answer/sproce ss/refinebox" under STDB folder.
- 2.Change copied project's name to "extract\_xj"
- **3.**Open this project and start Ligament Layout Editor.
- 4.Insert insert command the last etch command and define parameters :



Variables & Macros | Flow | Unfolded Flow

Names	Arg
Ė·······Ē <mark>Flow</mark>	
PP #header	
主 environment	title
substrate	dopant
comment	text
PP #endheader	
deposit 📥	material
📥 📥 deposit	material
pattern	layer
etch	material
etch	material
<b></b> #if	
insert	dios
+++ #endif	
implant 🗽	species
-anneal	time
insert	dios
L	basename



# Ex: extracting Xj (2/2)

5. Specify sprocess command in **insert** command like below:

```
select z=\"NetActive\"
set x0 \[interpolate Silicon y=2 value=0\]
set x1 \[lindex \$x0 0\]
set x2 \[interface Oxide /Silicon y=2\]
puts \"DOE: Xj_um \[format %.3f \[expr (\$x1 -\$x2)\]\]\"
```

Caution
 \ are needed before some special symbolic character, [, ], " and \$ because Ligament cannot recognize special character without \.

6. Save and close Ligament Flow Editor and run the project.



## Ex: extracting Xj ~the result~

#### • Extracted value is displayed on swb.

Project	Scheduler				
	Family	/ Tree	Variable Values		
	<b>Senia</b>	<b>L</b> urusP			
	spro	cess			
		refine	Xj_um		
1	0		0.325		
2	1		0.316		
	1				



#### **Changing diffusion models**





# **Diffusion Models**

#### • The ChargedPair diffusion model: (default)

- > Used for high dose amount of implantation. (damage is high.)
- Used for short-term anneals.
- Used for advanced CMOS processes as they represent a balance between accuracy and computational expense.

#### • The ChargedFermi diffusion model:

- Used for low dose amount of implantation. (damage is low.)
- > Used for long-term high-temperature anneals.
- The calculation time is faster than ChargedPair diffusion model.

The detail of model is introduced in 2D Advanced Sentaurus Process course.



# **Change Models**

The command to change the diffusion model is :

pdbSet Silicon Dopant DiffModel ChargedFermi

#### Simulators and available diffusion models

	SProcess	Dios	TSuprem4
1-Stream	ChargedFermi SetDiosEquilibriumModelMode	Equilibrium <default></default>	NSTREAMS=1 <default></default>
3-Streams	ChargedPair <default> SetDiosPairModelMode</default>	PairDiffusion	NSTREAMS=3

#### **Caution!**

The default model is different between each simulator. ChargedFermi model is generally appropriate for power device.



# **1D Example**

- Copy project "1D\_SProcess" from training\_library
- Refer to the command file of example "1D\_SProcess"
- Check 1D doping profile by INSPECT
- Output file introduction



# **2D Example**

- Copy project "2D\_SProcess" from training\_library
- Refer to the command file of "2D\_SProcess"



#### **2D Example Process Flow**





### **2D Example Mesh Setting**



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#### **Extract Parameters**

Ygox (X coordinate of oxide/silicon interface) Ypol (X coordinate of POLY/oxide interface) Tox (gate oxide thickness) = Ygox-Ypol Lgeff (effective channel length) = 2\*Xgd Xj (Source/Drain junction depth)





### **Implement External Variables on SWB**

 copy 2D\_SProcess > clean up > add parameters > modify command file > clear up & renumber the experiment tree

	No Variables	Add external parameters on workben	ch
SemiaurusP         Add,        Delete        Propert.        Add Val        Add Val	Ins Del ies Ues lues Value	Add Parameter   Parameter:   Default Value:   0,18     OK     Cancel	
	Family Tree	Variable Values	

	railitty 1166				Variabit	s varues		
SentaurusP								
		lgate	HaloDose	HaloEnergy	Lgeff	Xj	Ygox	Tox
1		0,18	1e13	15	1.571e-01	1,984e-01	6.497e-04	3.331e-03



#### **Implement External Variables on SWB**

 copy 2D\_SProcess > clean up > add parameters > modify command file > clear up & renumber the experiment tree



Link external variables to internal variables



#### **Tecplot SV**





### **Overview**

- Tecplot is software for scientific visualization that has been extended by Synopsys to accommodate the special requirements of TCAD simulations.
- Synopsys provides an original equipment manufacturer (OEM) distribution of Tecplot that includes the original Tecplot distribution by Tecplot, Inc., the Synopsys TCAD add-on, and the Synopsys tecplot\_sv launcher, which starts Tecplot in a special Synopsys configuration mode.
- The complete package consisting of these three components is called Tecplot\_SV.



# Starting Tecplot\_SV

- to start Tecplot\_SV:
  - > tecplot\_sv &

- > tecplot\_sv <filename> &
- in SWB : select Visualize  $\rightarrow$  .tdr Files  $\rightarrow$  Tecplot SV



### **Screen Elements**





# **View Control**

- zooming: click on the zoom tool and draw a rubber band, or use the middle mouse button and drag the pointer downwards/upwards for zoom in/out
- click on "last view" to return to the previous view, control-f fits the entire structure into the view window
- move the structure by holding the right mouse button and dragging the pointer



# **Displayed Objects**

- Select both Silicon and Oxide in the Material list. Hold the Ctrl key to highlight both items.
- Click the Display Exclusive button to display these two material regions only and to switch off the display of any other regions.
- To limit the operations to only a specific region, click the Region List/Material List button to switch to the Region list, which selection by region.
- Click the Mesh On button.
- Click the Contours Off button on the sidebar to switch off any field that is currently displayed on the structure.





# **Data Sampling**

 After a device structure has been loaded in Tecplot, the values of the physical fields existing on the structure can be seen using the data probing tool on the sidebar.



Y Probe			//////// ×
Var Values	Zone/Cell Info		
Cell Center	Face Neighbor		
📕 One Line p	er Variable		
	Variable	Value	
v v	1: X	-0.015	
V V	2: Y	0.0417671	
V V	3: Z	0.041773	
V V	4: ElectrostaticPotential	0.925776	
V V	5: eDensity	0	
V V	6: hDensity	0	
V V	7: LatticeTemperature	300	
V V	8: eCurrentDensity-X	0	
V V	9: eCurrentDensity-Y	0	
V1	0: eCurrentDensity-Z	0	
	Scroll Up Scroll Dn		
Zone: 4 : 1: S	pacer.x (Nitride)		
			Probe At
	Close	Help	



# **Generating 1D Cuts**

- Before a cut is made, it is necessary to decide whether the data obtained from the cut should go to an existing frame or a new frame.
  - Frame > Frame Linking. The Set Links for Current Frame dialog box is displayed
  - Select Slice Positions and click Apply Settings to All Frame, of this Group.
- One-dimensional cuts can be made along either the x or y coordinate axes
  - For example, to sample data along the x-axis, select the Orthogonal Cut (Y for normal direction) function



# **Generating Multiple Cuts in One Step**

- Multiple cuts in parallel to each other can be generated in one step.
- Slicer > Y Normal Cuts

♥ Orthogonal Cut	×
Normal Direction:	<ul> <li>↓ X</li> <li>↓ Y</li> <li>↓ Z</li> </ul>
□Cut at mouse positio	on
Number of Cuts: First Cut At: Last Cut At:	(ἔ ▲ 0.05ἔ ▲ 0.15፪ ▲
<ul> <li>♦ Merge Zones in Cu</li> <li>↓ Cut Zone By Zone</li> </ul>	ıt
Create Cut	Cancel



# **Working with Frames**

- For each successfully loaded data file, Tecplot starts a new frame and associates the frame with the loaded data. In addition, Tecplot SV automatically opens up new frames for newly generated cuts, either 1D or 2D.
- Tecplot permits multiple frames in the same workspace to be managed in a coordinated manner. These functions and commands are available from the Frame menu and are convenient to use. For example:
  - To send a frame to the back and bring another to the front: Frame > Push Current Frame Back.
  - To simultaneously show all the frames:
     Frame > Arrange Frames and select one of the options.



#### frames to be linked by one or more of their common frame attributes.

 Changing an attribute in one frame results in the same change to all other frames linked with respect to that attribute.

The frame linking feature of Tecplot SV allows multiple

- To link frames:
  - Click the All Frames button on the sidebar.
  - Click the Link button.
  - To break the link, click Unlink button.

# Frame Linking







# **Synchronized Cuts**

 In addition to appearance coordination, linking allows synchronized cuts to be made simultaneously on all linked

structures.





### Sentaurus Structure Editor – Building Meshes (SDE)




#### **Overview**

- SDE is a structure editor for 2D and 3D device structures.
- From the graphical user interface, 2D and 3D device models are created geometrically, using 2D or 3D primitives, such as rectangles, polygons, cuboids, cylinders, and spheres.
- Rounded edges are generated by filleting, 3D edge blending, and chamfering. Complex shapes are generated by simply intersecting primitive elements.
- The graphical user interface of SDE features a command-line window, in which it prints script commands corresponding to the GUI operations.
- In process emulation mode (PROCEM), SDE translates processing steps, such as etching and deposition, patterning, fill and polish, into geometric operations.
- PROCEM supports various options, such as isotropic or anisotropic etching and deposition, and rounding and blending.



#### Modules of SDE

- Structure creation via primitives
- Process emulation with PROCEM (3D only)
- Contact definition
- Doping definition
- Mesh definition



# Starting SDE in GUI Mode

 To start SDE, on the command line, enter:

sde

sde -2D

V Sentaurus Struc	ture Editor⊕ Inx vX	-2005,10				- 0 ×
Ele Edit View Draw	Mesh Device Contac	ts <u>H</u> elp				
] 🗅 🖙 🔒 ] 😕			🖂 ] 🕽 🙆 🞑	ର ଅନ୍କର 🖉 🖸 🖸 🖸	00012	
Silicon	base	none	Select Body			
P						
>						
×						-
LUV .						fli



#### **Creating Regions**

• To create a rectangular region:

- Draw > Create 2D Region > Rectangle, or click the corresponding toolbar button
- Click and drag a rectangle
- Command line:

```
(sdegeo:create-rectangle
  (position 0 0 0)
  (position 1 1 0)
  "Silicon" "region_1"
)
```



# **Creating Polygons**

- To create a polygonal region:
  - Draw > Create 2D Regions > Polygon, or click the corresponding toolbar button.
  - Click a location in the view window where the first vertex of the polygon is to be placed.
  - Repeat the previous steps for all the other vertices except the last vertex of the polygon.
  - For the final vertex, click the middle mouse button to place it.

```
(sdegeo:create-polygon
  (list (position 0 0 0)
   (position 0 1 0)
   (position 1 2 0)
   (position 1 0 0) )
  "Silicon" "region_2"
```



#### **Selecting Materials**

- All materials used by Sentaurus Structure Editor are accessible from the Material list.
- To set the material to be used for new objects:
  - Click the Material list and select the required material, for example, Silicon.

Silicon	\$
PolySilicon	
Resist	
Si3N4	
SiO2	
Silicide	
Silicon	
SiliconCarbide	
SiliconGermanium	
Silver	<b>_</b>
Solder60_40	•



#### **Exact Coordinates Mode**

- In Sentaurus Structure Editor, geometric objects can be drawn manually. However, for most applications, it is necessary to specify explicitly the coordinates of the object
- To do this, it is necessary to activate the Exact Coordinates mode.
  - Draw > Exact Coordinates.
- When the mode is active, all subsequent command operations that involve the placement of any object will display a dialog box in which exact coordinate values can be entered for the object being edited.



# Selecting the Default Boolean Expression

- When the Sentaurus Structure Editor GUI is used to build a device with multiple regions, the later-added regions may intersect existing regions.
- A predefined scheme is required to resolve the overlapping region.
- Draw > Overlap Behavior > New Replaces Old, or click the corresponding toolbar button.



New replaces old



#### **Types of Boolean Expressions**

#### • Merge

(sdegeo:set-default-boolean "AB")

New Replaces Old

(sdegeo:set-default-boolean "ABA")

Old Replaces New

(sdegeo:set-default-boolean "BAB")

New Overlaps Old

(sdegeo:set-default-boolean "ABiA")

Old Overlaps New

(sdegeo:set-default-boolean "ABiB")



#### **Rounding Edges**

- To round corners of regions:
  - Click the Selection Level list and select Select Vertex.
  - Click the Aperture Select button in the toolbar.
  - Click the upper-left corner of the spacer to highlight the vertex.
  - Edit > Edit 2D > Fillet. Enter fillet radius.
  - The selected corner is now rounded.

```
(sdegeo:fillet-2d
 (list (find-vertex-id (position 0 1 0))
 )
 0.2
)
```



# **Defining Contacts**

- To define a contact:
  - Contacts > Contact Sets.
  - Define the properties of the contact. Enter the name of the contact in the Contact Name field.
  - Click Set to add the contact to the Defined Contact Sets list. Multiple contacts can be defined in one session.
  - Click Close.

(sdegeo:define-co	ntact-set "gat	ce" 4 (color:rgb 1 0 0 )
" # # " )	Contact Sets	
	Defined Contact Sets none gate source drain substrate bodytie	Contact Name:  bodytie Edge Color: 1.000000 0.000000 1.000000
	Activate	Edge Thickness: 4.000000 Face Pattern: ## \$



#### **Associating Contacts with Edges**

- Contacts become effective only after they are associated with an edge of the device structure:
  - Activate a contact by selecting it from the Contact list.
  - Set the selection level to Select Edge in the Selection Level list.
  - Click the Aperture Select button.
  - Click the edge of the structure where the contact, for example, source, will be defined. The selected edge is now highlighted.
  - Contacts > Set Edge(s). This defines the selected contact at the highlighted edge. The edge is now characterized by the color and line styles previously set for the contact.

#### (sdegeo:set-current-contact-set "gate")

(sdegeo:set-contact-edges edge-list "gate")





## **Defining a Region as a Contact**

- To turn an entire region into a contact:
  - Select the contact from the Contact list.
  - Set the selection level to Select Body in the Selection Level list.
  - Click the Aperture Select icon on the toolbar.
  - Click the region where the contact is to be defined, for example, the poly gate region.
  - Contacts > Set Region Boundary Edges. This converts the selected region into a contact. The edges of the region have changed to the color and style of the selected contact.
  - To remove the gate region, select the region and Edit > Remove > Region

```
(sdegeo:set-current-contact-set "gate")
(sdegeo:set-contact-boundary-edges entity-list)
```



# **Defining Constant Doping**

- To define a uniform doping profile in a region:
  - Device > Constant Profile Placement.
  - Type a name in the Placement Name field.
  - In the Placement Type group box, select Region, and select the region.

```
(sdedr:define-constant-profile "CProfileDef_1"
   "BoronActiveConcentration" 1e15)
(sdedr:define-constant-profile-region "CProfile_1"
   "CProfileDef_1" "region_1")
```



#### **Constant Profile Placement**

- In the Constant Profile Definition group box, type a name in the Name field.
- Select species from the Species list.
- Enter value in the Concentration field.
- Click Add Placement.
- Click Close.

Constant Profile	Placement	
Placement Name	Place C D. Epi	\$
-Placement Type	]	-Visualization
📿 Ref/ Win	\$	Show
Region	R.Siliconepi	
🔾 Material	Silicon	Hide
Name Const.	Epi BoronActiveConcentration	÷
Concentration	1e+17	
Decay Factor		Replace
	,	



## **Defining Analytical Profiles**

- The placement of an analytic profile is performed in two steps:
  - Define the baseline. The baseline is used to determine the lateral extent of the profile and can also serve as the reference point for the depth of the peak position.
    - Mesh > Define Ref/Eval Window > Line.
    - In the view window, click the first point of the baseline.
    - Click again to define the end point of the baseline.
    - In the displayed dialog box, enter the name for the baseline and click OK

```
(sdedr:define-refinement-window "Myline" "Line"
  (position 0 0 0) (position 1 0 0)
)
```



#### **Analytical Profile Placement**

Define the shape of the profile itself.

- Device > Analytic Profile Placement.
- Type the Placement Name field.
- Select the baseline from the Ref/Win list.
- In the Profile Definition group box, enter the Name field.
- Select the Gaussian option from the Profile Type list and species from the Species list.
- In the Concentration group box, fill in Peak Concentration, Peak Position, Junction and Depth.
- In the Lateral Diffusion group box, enter the Factor field.
- Click Add Placement.



## **Analytical Profile Placement**

```
(sdedr:define-gaussian-profile
"AProfileDef 1" "BoronActiveConcentration"
"PeakPos" 0
"PeakVal" 1e20
"ValueAtDepth" 1e15
"Depth" 0.1
"Erf" "Factor" 0.8
(sdedr:define-analytical-profile-placement
"AProfilePlacement 1"
"AProfileDef 1"
"Myline"
"Both" "NoReplace" "Eval"
```



# **Defining Mesh Strategies in Regions**

- To define a meshing strategy in a device region:
- Mesh > Refinement Placement.
- The Refinement Placement dialog box is displayed. It includes two input files:
- Refinement Definition group box includes fields for defining the meshing strategy and
- Placement Type group box deals with the placement.

Refineme	ent Placen	ient				
Placement Na	ame	PlaceRf	F.Epi		<b>\$</b>	
-Placement	Туре ———					
🔾 Ref/	Win	BaseLin	ne.Source	¢	Shov	
💽 Regi	ion	R.Silico	nepi	•		
📿 Mate	erial	Silicon		¢	Hide	·
-Refinement Name	t Definition — RefDef.Epi			¢	)	
		_	X Direction	Y Direction	Z Direc	tion
Max Elem	ient Size	0	).100000	0.012500		
Min Eleme	ent Size	lo	0.005000	0.005000		
Refineme	ent Functions					
Doping	(Concentratio	n	Value Diffe	erence	<b>•</b> 1	
Functio Doping	n Concentratior	1	Criteria Value Difference	Value 1.000000		Add
Chang	ge Placement		Delete Placeme	nt		Close

**211111**2

Predictable Success

## **Doping Refinement Placement**

```
(sdedr:define-refinement-size
"RDef 1"
0.1 0.1 0.1
0.01 0.01 0.01
(sdedr:define-refinement-function
"RDef 1"
"DopingConcentration"
"MaxTransDiff" 1
(sdedr:define-refinement-region
"RPlacement 1"
"RDef 1"
"region 3"
```



#### **Defining Refinement Windows**

- In SDE, a meshing strategy can be restricted to only selected areas.
- The areas (refinement windows) need to be defined first before a meshing strategy can be applied.
- Mesh > Define Ref/Eval Window > Rectangle.



#### **Refinement windows**

```
(sdedr:define-refinement-window
"Rwin1" "Rectangle"
(position 0 0 0) (position 1 1 0)
(sdedr:define-refinement-size
"RDef 1"
0.1 0.1 0.1
0.01 0.01 0.01
(sdedr:define-refinement-placement
"RPlacement 1" "RDef 1" "Rwin1"
```



# **Defining a Multibox Mesh Strategy**

- Some applications require meshing strategies in which meshing line densities are gradually changed.
- SDE supports another type of meshing strategy called multibox refinement strategy:
- Mesh > Multibox Placement.

Y	Multibo>	( Placement						X
	Placement N	lame (	PlaceMB.Channel			¢		
	-Placement	Туре ———			-Visualization			
	Ref/Win	RefWin.	Channel	•	Show		Hide	
	-Multibox E	Definition ———						
	Name	MB.Channel			\$			
		×		٧		Z		
	Max	0.050000	Max	0.012500	Max			
	Min	0.025000	Min	0.000100	Min			
	Ratio	1.000000	Ratio	1.350000	Ratio		_	
	Chan	ge Placement	Delet	te Placement	]	(	Close	



#### **Meshing the Device Structure**

To call the meshing engine:

 Mesh > Build Mesh.

Build Mesh Save Grid to File:	Browser
ı ⊢ Meshing Engine-	Mesh Viewer
MESH	○ NOFFSET ● SDE ○ tecplot_sv ○ none
Mesh options:	
Option	Description
-discontinuousDat	a Write discontinuous data sets.
-f	Fit MaxElementSize first. MESH creates an initial set of macro-elements according to the user
-1	Do not use profiles. Neither analytical nor external profiles are taken into account. The .dat file
-m	Generate grids using only the device geometry as the refinement criterion and ignoring doping
-P	New Delaunization algorithm to finish the mesh (recommended for 3D, ignored in 2D).
-R	Remove unnecessary points, edges, or faces from boundary description
-3	Produce more restrictive Delaunay grids. The maximum angle allowed for triangles is pi/2 in 2D.
-t	Use only simplex elements: triangles in 2D and tetrahedra in 3D.
Other options:	
	Build Mesh Cancel



#### Basic Flow with result of process simulation

- The SSE flow is as follows:
  - 1. Read boundary
  - 2. Contact definition
  - 3. Ref/Eval Window definition
  - 4. Read profile
  - 5. Mesh definition
  - 6. Build Mesh
- These operations and commands will be introduced from next slide.



## **Meshing for Device Simulation**

• possible flows:

SP or TS4 process simulation SDE: -read boundary -read doping -specify new mesh criteria -call mesh engine -save structure + doping



SDE:

-boundary definition -doping definition -mesh criteria definition -call mesh engine

-save structure + doping





#### **Read boundary**

#### • Read the boundary to be modified.

	🗙 Model Input	×
<u>File Edit View D</u> raw <u>M</u> esh <u>D</u> evice	Look in: 🔄 /Training_Sample/PostBasic/answer/sse/nmos_rolloff_sse/ 🗹 🗲 💼 📸	<b>*</b>
☐ <u>N</u> ew Ctrl+N pilicon	🛄 📄 n5_fps.tdr	
🔚 Save Model Ctrl+S	n2_fps.tdr n6_fps.tdr	
- Save Model <u>A</u> s Save Boundary	n3_bnd.tdr in7_bnd.tdr in7_fps.tdr	
Save Boundary <u>A</u> s Import	n4_bnd.tdr	- 1
Print Ctrl+P	n5_bnd.tdr	
Journal 🔛	File name: n2_bnd.tdr	]pen
- Exit Ctrl+Q	File type: TDB Boundary Files (*.tdr)	ancel
		///
<u>sdeio:read-tdr-</u>	ond "n2_bnd.tdr")	



# Contact definition (1/2)





## Contact definitions (2/2)

choose the center of the t **3.** Select contact region (metal) and set region boundary edge from contacts menu.

(sdegeo:set-contact-boundary-edges. (list(car(find-body-id(position 0.29 -0.002 0.0))) "drain" )





#### **Ref/Eval window definition**

Help Device Contacts Define Bef/Eval Window Define the region for 🛏 Line Delete Ref/Eval Window Rectangle mesh and profile. Refinement Placement... 🛆 Polygon Multibox Placement... Cuboid Noffset Parameters... 🔄 From Face Clear All Global Refinement... There are 3 window types, rectangle, line and polygon for 2D. (sdedr:define-refeval-window "win\_device" "Rectangle" (position 0 -0.2 0) (position 0.3325 1 0)



#### **Read profile**

Read the profile data generated by process simulator.







## Mesh definition (1/2)





#### Mesh definition (2/2)







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#### **Build Mesh**

#### Build mesh for device simulation.







#### Appendix ~Cut structure~

 Cut the unnecessary region for device simulation





(sdegeo:2d-cut

# Meshing with SDE + SMesh

#### • example: project SimpleMesh

refinement criteria for a region

```
<structure, doping ...>
(sdedr:define-refinement-size "Sub1.Def"
0.2 0.2 0.05
0.05 0.1 0.05
)
(sdedr:define-refinement-region
"Sub1.Pl"
"Sub1.Def"
"Substrate")
```

← a name for this criterion
← maxx maxy maxz
← minx miny minz

```
←placement_name
<refinement_name,
<region_name</pre>
```


refinement in a box

(sdedr:define-refinement-window "Sub2.Win" "Cuboid" (position xboxr 0.15 0.0) (position xbox 0.0 zbox)) (sdedr:define-refinement-size "Sub2.Def" 0.05 0.1 0.025 0.02 0.05 0.025 (sdedr:define-refinement-placement "Sub2.Pl" "Sub2.Def" "Sub2.Win")

- $\leftarrow$  a name for this criterion
- $\leftarrow$  first corner
- $\leftarrow$  opposite corner
- $\leftarrow$  maxx maxy maxz
- $\leftarrow$  minx miny minz

- $\leftarrow placement\_name$
- $\leftarrow$  refinement\_name,
- $\leftarrow region\_name$







graded mesh ("multibox method")





refinement on a field (doping)

(sdedr:define-refinement-size "Doping.Ref" 0.5 0.5 0.2 0.004 0.004 0.2) (sdedr:define-refinement-function "Doping.Ref" "DopingConcentration" "MaxTransDiff" 1) (sdedr:define-refinement-region "Doping.Pl" "Doping.Ref" "Substrate")

← min/max desired spacing in x,y,z

← apply criteria to field
 "DopingConcentration"
 ← criterion: maximum
 difference

← apply criteria in region"Substrate"







 finally: save boundary, write input file for "smesh", call the mesh engine

```
(sdeio:save-tdr-bnd (get-body-list) "n@node@_bnd.tdr")
```

(sdedr:write-cmd-file "n@node@\_msh.cmd")

(system:command "smesh n@node@\_msh")



## Flow of Input and Output in SDE





## MOSFET Mesh Setup Strategy (for SDevice Simulation)

- Load boundary from previous SProcess output
- Define initial mesh for Silicon and PolySilicon materials
- Refine Source/Drain junction mesh
- Refine LDD junction mesh
- Refine silicon surface region between channel to S/D contact
- Define gate oxide mesh
- Refine channel mesh
- Refine PolySilicon mesh
- Load doping profile from previous SProcess output
- Define PolyGate (PolySilicon) doping





### MOSFET Mesh Setup Result (for SDevice Simulation)



## **Interactive Mode**

- Start Structure Editor => type "sde"
- Journal on => record the command line of each step
- Import boundary file from n4\_bnd.tdr
- turn off "auto region name", turn on "exact coordinates"
- Step by step setup mesh by GUI
  - Silicon => (0.1, 0.1) / (0.05, 0.1)
  - Poly => (0.02, 0.05) / (0.01, 0.025)
  - SD\* => (0.09, 0.0) / (0.49, 0.3) => (0.1, 0.03) / (0.006, 0.006)
  - LDD => (0.05, 0.0) / (0.09, 0.05) => (0.006, 0.006) / (0.005, 0.005)
  - CtoC => (0.09, -0.002) / (0.49, 0.006) => (99, 0.002) / (66, 0.001)
  - Gox => (0.0, -0.002681) / (0.09, 0.00065) => (99, 4e-4) / (66, 4e-4)
  - Channel => (0.0, 0.00065) / (0.09, 0.075) => (0.02, 0.05) / (0.01, 2e-4) / (-1.45, 1.45)
  - Gate => (0.0, -0.18) / (0.09, -0.002681) => (99, 0.04) / (66, 4e-4) / (0.0, -1.75)
- Load sub mesh (geometry and doping data) from n4\_fps.tdr
- Define PolyGate doping type and concentration (Arsenic 6e19)
- Save
- Build mesh
- Journal off
- Check .tdr .jrl



### **Batch Mode**

- Refer to command file "sde\_dvs.cmd" of example 0.18um\_nMOS
- Check output files



### **The Final Mesh for SDevice**





### **Sentaurus Device (SDevice)**





## Outline

- Flow of input and output in SDevice
- Command file introduction
- Parameter file introduction
- Physical Models in Device Simulation
- Solution Modes in Device Simulation
- 0.18um nMOS Id\_Vg example

### Flow of Input and Output in SDevice





## **Command File**

File "define the input and output files of the simulation " Electrode { "define electrical (or thermal) contacts, initial bias condition, special boundary condition" Physics "declare physical models" Plot "specify the solution variables that are to be saved in the Plot file" Math "options of numeric solver" Solve set bias sweeps sequence and solve transport models"



#### **Overview of SDevice Commands**





## What Can Sentaurus Device Do?



- 1D, 2D, and 3D simulations.
- Electrical, thermal, and optical characteristics.
- Silicon-based and compound semiconductor devices.
- Mixed-mode simulations.



## **Sentaurus Device Flow**





## Ex 1. Run NMOS Roll Off Project

Project: /PostBasic/question/sdevice/nmos\_rolloff\_sdevice

- Open the input command file, and close it.
- Run and observe Id-Vg curves.

i <u>m</u> ents	<u>N</u> odes	Va <u>r</u> iable	es <u>O</u> ptimization	Calibration	Extensions	<u>H</u> elp	
	•		- <b>X- ,11 ,-1</b>	≣ ▼ @>▼ 🚺	<b>S</b>	• • ×	
Project	Scheduler			Run			
		Family Tree					
	SentaurusP sprocess			SentaurusS		SentaurusD	
				sde		ldVg	
			Lgshift				
1			0.0				
2			0.005				
3			0.01				
4			0.0175				
5			0.0325				
6			0.0925				



## **NMOS Roll Off Project**

Project: /PostBasic/question/sdevice/nmos\_rolloff\_sdevice Description: Simulate NMOS Id-Vg characteristics.





## **Input Command File**

- The input command file typically contains the following sections:



#-ramp gate: Quasistationary ( MaxStep=0.01



# File Section (1/2)

Define the input and output files of the simulation.





# File Section (2/2)

### • grid =

>The grid and doping profile of the device structure.

#### parameter=

≻The model parameter file.

#### • plot =

≻The final spatial variable data file.

#### current=

≻The electrical output data file.

output =
The output log file.



# **Electrode Section (1/3)**

Define the electrical contacts of the device, together with their initial conditions



• Name=

Define the contact name.

Voltage=

>Define a voltage boundary condition with an initial value.



## **Electrode Section (2/3)**

Main Options:

### • Barrier=

Define the workfunction difference between the intrinsic silicon material and the (highly doped) polysilicon gate when remove polysilicon. For N+ polysilicon, this value is approximately -0.55 eV.

### Current=

Define a current boundary condition with initial value [A] (Current=I/AreaFactor).

### • Charge=

Define a floating electrode with a charge boundary condition and an initial charge value [C] (Charge=C/AreaFactor).



# **Electrode Section (3/3)**

Main Options (continued):

• Resistor=

>Define a series resistance [  $\Omega$  ] (Resistor=R\*AreaFactor).

eRecVelocity=

Define a recombination velocity at a contact for electrons (hRecVelocity for holes).

Schottky

> Define an electrode as a Schottky contact.

AreaFactor=

Specify a multiplication factor for the current in or out of an electrode, 1um by default.



# Physics Section (1/2)

Declare physical models to be used in the simulation.

Physics {
 EffectiveIntrinsicDensity ( OldSlotboom )
 Mobility(DopingDependence HighFieldSaturation Enormal)
 Recombination (SRH (DopingDependence) Auger)
}

- Physics section can be set for Material, Region, MaterialInterface and RegionInterface.
- The EffectiveIntrinsicDensity statement activates the silicon band-gap narrowing effect in highly doped regions. The model directly affects the calculation of the intrinsic carrier density in silicon.



## Physics Section (2/2)

- Mobility models include doping dependence, high-field saturation (velocity saturation), and transverse field dependence.
- Recombination models are specified.
- About mobility models and recombination models, more explanations will be done in the later training.



## **Plot Section**

Specify the solution variables that are to be saved in the Plot file.

Plot {
 eDensity hDensity eCurrent hCurrent
 Potential SpaceCharge ElectricField/Vector
 eMobility hMobility eVelocity hVelocity
 Doping DonorConcentration
 AcceptorConcentration
}



- An extensive list of optional plot variables is in Appendix F of SDevice manual (A-2008.09).
- To save a variable as a vector, append /Vector to the keyword.



# Solve Section (1/10)

Defines a sequence of solutions to be obtained by the solver.

```
Solve {
 #-initial solution:
 Poisson
 Coupled { Poisson Electron Hole}
 #-ramp drain:
 Quasistationary (MaxStep=0.1
                    Goal { Name="drain" Voltage=0.05 } )
                    { Coupled { Poisson Electron Hole} }
 #-ramp gate:
 Quasistationary (MaxStep=0.05
                    Goal { Name="gate" Voltage=1.2 } )
                    { Coupled { Poisson Electron Hole} }
}
```



## Solve Section (2/10)

Coupled { Poisson Electron Hole }

- The drift-diffusion transport model is used, it solves self-consistently the coupled Poisson and carrier continuity equations.
- Other transport models include thermodynamic, hydrodynamic transport, etc., using these models can improve simulation accuracy, however usually simulation time increases, and sometimes it becomes difficult to converge.



## Solve Section (3/10)

### **Thermodynamic Transport**

- Solve the lattice temperature equation in addition to the Poisson and carrier continuity equations. Coupled { Poisson Electron Hole Temperature }
- Some devices, as power devices, can occur self-heating phenomenon, and need to specify the Thermodynamic transport model.





## Solve Section (4/10)

### Hydrodynamic Transport

- Solve the carrier temperature equations in addition to the Poisson and carrier continuity equations. Coupled { Poisson Electron Hole eTemperature hTemperature }
- The deep submicron MOSFETs need to specify the hydrodynamic transport model.



Predictable Succes

# Solve Section (5/10)

 There are two Quasistationary statements in this Solve command. The first one ramps the drain voltage to 0.05 V (from 0 as defined in the Electrode section). Similarly, the second sweeps the gate bias from 0 to 1.2 V.



# Solve Section (6/10)

### **Quasistationary Analysis Syntax:**




# Solve Section (7/10)

- Internally, the Quasistationary command works by ramping a variable t from 0.0 to 1.0. V=V<sub>0</sub>+t(V<sub>1</sub>-V<sub>0</sub>), where V<sub>0</sub> is the initial voltage and V<sub>1</sub> is the final voltage, which is specified in the Goal statement.
- InitialStep controls the size of the first step of the ramping (0.1 by default). 0.01 is recommended.
- MaxStep (1 by default) and MinStep (0.001 by default) limit this change.
- The rate of increase is controlled by the factor Increment (2 by default).
- The rate of decrease is controlled by the factor Decrement (2 by default).



# Solve Section (8/10)



Increment=2 (default)
 ✓ If it converges at t=0 and t=a points, then it will go to t=3a point.

- Decrement=2 (default)
   > If it fails at t=3a point, then it comes back to t=a point, and this time it will try x=2a point.
- MinStep and MaxStep can forcibly limit their movements.
- When the step is smaller than MinStep, then it fails to converge.



# Solve Section (9/10)

• This is a part of out file:

```
Computing step from t=0.0000e+00 to t=0.1 (Stepsize: 0.1) :
Computing Coupled(1 poisson-equation(s), 1 electron-equation(s),
          1 hole-equation(s) )
using Bank/Rose nonlinear solver.
        voltage electron current
                                  hole current conduction current
contact
                                   -6.408E-36
gate
         0.000E+00 6.408E-36
                                                 0.000E+00
substrate 0.000E+00 2.615E-15
                                    -2.213E-17
                                                  2.592E-15
drain 5.000E-03 4.786E-11 1.357E-21 4.786E-11
source 0.000E+00 -4.786E-11 -4.701E-27 -4.786E-11
Computing step from t=0.1 to t=0.2 (Stepsize: 0.1) :
```

- The drain voltage changes from 0V to 0.05V.
- When t=0.1, the drain voltage = 0.005V.



### Solve Section (10/10)



• I-V Curve's smoothness can be improved by decreasing MaxStep.



# Math Section (1/2)

Control the numeric solver in the simulation.

```
Math {
  Iterations=20
}
```

```
Extrapolate *off by default
               *default = 50
```



Extrapolate

 $\succ$ In quasistationary bias ramps, the initial guess for a given step is obtained by extrapolation from the solutions of the previous two steps.

Iterations

 $\triangleright$ A maximum of Newton iterations are specified. 20 is recommended.



# Math Section (2/2)



If  $|\Delta x| < error$ , then it converges.

• Given a function f(x) and its derivative f'(x), we begin with a first guess  $x_0$ . A better approximation  $x_1$  is

$$x_1 = x_0 + f(x_0)/f'(x_0)$$

• The function *f* is shown in blue and the tangent line is in red). We see that  $x_{n+1}$  is a better approximation than  $x_n$ for the root x of the function f.



### **Additional Features**





### **Edit the Model Parameters**

- If you need to use user-defined values for model parameters, you must edit the parameter file.
- To generate a copy of the default parameter file of Silicon, type on the command line:
  - \$ sdevice -P(for Silicon)\$ sdevice -P:GaAs(for GaAs)

$\bigcirc$			Terminal				×
<u>F</u> ile	<u>E</u> dit	<u>V</u> iew	<u>T</u> erminal	Ta <u>b</u> s	<u>H</u> elp		
[wang	gz@war	ngz-p4	70-lnx /	]\$ sde	vice ·	-P[]	÷.

- The above commands generate the default parameter file models.par.
- If user defines parameter = "@parameter@" in the File Section of the input command file, it will lead to the file sdevice.par.
- User can other parameter file name, for example, parameter = "silicon.par"
- The user-defined parameter file should only contain the user-defined values for model parameters.



### Define Multi-Material Model Parameters In a Parameter File

• User can define multi-material model parameters in a parameter file as follows.

```
Material="AlGaAs" {
    Epsilon {
        ...
     }
}
Material="GaAs" {
    Epsilon {
        ...
    }
}
```



## **Ex 2. Change the Electron Lifetime**

Project: /PostBasic/question/sdevice/nmos\_parameter

- Open the parameter file. Because parameter = "@parameter@" is defined in the File Section, then it leads to the file sdevice.par.
- Edit sdevice.par as follows:

```
Scharfetter
{ taumin = 0.0000e+00 , 0.0000e+00 # [s]
    #- taumax = 1.0000e-05 , 3.0000e-06 # [s]
    taumax = @taumax@ , 3.0000e-06 # [s]
    Nref = 1.0000e+16 , 1.0000e+16 # [cm^(-3)]
    gamma = 1 , 1 # [1]
    Talpha = -1.5000e+00 , -1.5000e+00 # [1]
    Tcoeff = 2.55 , 2.55 # [1]
    Etrap = 0.0000e+00 # [eV] }
```



• Define the parameter taumax in the SWB, set its value as 1e-07. Run the nmos\_parameter project.



### Plot Statement In the Solve Section (1/2)

```
Solve{
  Quasistationary(
  ){ Coupled{ ... }
      Plot(
         FilePrefix="n@node@" NoOverWrite
         Time = (0.1; 0.3; 0.8)
   }
```

 Plotting or saving a solution during a (DC or transient) sweep at a set of given values of the t variable. for example, 10%, 30%, 80% of the goal.



### Plot Statement In the Solve Section (2/2)

```
Solve{
  Quasistationary(
  ){ Coupled{ ... }
      Plot(
          FilePrefix="n@node@" NoOverWrite
          Time=(Range=(0 1) Intervals=10)
    }
}
```

Plotting at regular intervals, for example, 0%, 10%, 20%, ..., 100% of the goal.



### Ex 3. Add Plot Statement

Project: /PostBasic/question/sdevice/nmos\_plot

• Add the following statement to the second goal of Solve section.

```
Plot(
    FilePrefix="n@node@" NoOverWrite
    Time=(Range=(0 1) Intervals=10)
)
```

 Run and observe tdr files. These tdr files are n@node@\_0000\_des.tdr, n@node@\_0001\_des.tdr,

n@node@\_0<del>010\_des.tdr,</del> n@node@\_des.tdr

t=0.2

0002

t=0.1

0001



Predictable Success

t=0

0000

### AreaFactor

- For the two-dimensional simulation, by default, SDevice assumes a 'thickness' (effective gate width along the z-axis) of 1um.
- The effective width is adjusted by specifying
   >an AreaFactor in the Physics section, or
   >an AreaFactor for each electrode individually.
- An AreaFactor is a multiplier for the electrode currents and charges.



## **CurrentPlot Section**

- Save variables at specified nodes or coordinates to the current file \_des.plt. The same variables can be selected as in the Plot Section
- It is possible to output averages, integrals, and the maximum and minimum of quantities over specified domains.
  - To do this, specify the keyword Average, Integrate, Maximum, or Minimum.
  - ≻Refer to SDevice manual for more information.

```
CurrentPlot {
    hDensity( (0 1) ) * hole density at position (0um, 1um)
    Potential (
        Average(Region="Channel") * average over a region
        Maximum(Material="Oxide") * maximum in a material
      )
}
```



### **Ex 4. Add CurrentPlot Section**

Project: /PostBasic/question/sdevice/nmos\_currentplot

Add the following section to the second goal of Solve section.
 CurrentPlot {



eDensity( (0 0.003) )

SYNOPSYS Predictable Success

### **Sweep Multi Voltages Simultaneously**





# **Physics Models**

- Mobility
- Generation-recombination





### Mobility Models (1/3)



 SDevice uses a modular approach for the description of the carrier mobility models. Silicon MOSFETs usually specify the following models.

Doping-dependent mobility model
 Mobility degradation at interfaces
 High-field saturation model



 Refer to SDevice manual (A-2008.09) for more information.
 Part II: Physics in Sentaurus Device CHAPTER 8: Mobility models



# Mobility Models (2/3)

#### **Doping-Dependent Mobility Model**

• Activated by

Physics{Mobility(DopingDependence ... ) ... }

• For doped materials, the carriers scatter with the impurities. This leads to a degradation of the mobility.

#### **Mobility Degradation At Interfaces**

Activated by

Physics{Mobility(Enormal ... ) ... }

• In the channel region of a MOSFET, the high transverse electric field forces carriers to interact strongly with the semiconductor-insulator interface.



### Mobility Models (3/3)

#### **High-Field Saturation Model**

Activated by

Physics{Mobility(HighFieldSaturation ... ) ... }

 Describe mobility degradation in high electric fields. In high electric fields, the carrier drift velocity is no longer proportional to the electric field.



### **Generation–recombination Models (1/3)**



- Generation-recombination processes are processes that exchange carriers between the conduction band and the valence band.
- Usually, Silicon MOSFETs need to be specified the following models:
   Shockley–Read–Hall (SRH) recombination
   Auger recombination
- The breakdown analysis must specify avalanche generation model.
- Refer to SDevice manual (A-2008.09) for more information.
   Part II: Physics in Sentaurus Device CHAPTER 9: Generation–recombination



### **Generation-recombination Models (2/3)**

#### **SRH Recombination**

Activated by

Physics{ Recombination(SRH ...) ...}

• SRH recombination through deep defect levels.



 The doping dependence of the SRH lifetimes is activated by

Physics{Recombination(SRH(DopingDependence...) ...) ...}



### **Generation–recombination Models (3/3)**

#### **Auger Recombination**

• The Auger model is activated by

Physics{Recombination(Auger ...) ...}

• Band-to-band recombination model. Typically important at high carrier densities.

#### **Avalanche Generation**

Activated by

Physics{Recombination(Avalanche ...) ...}

- Avalanche generation (impact ionization) requires a certain threshold field strength and the possibility of acceleration.
- The breakdown analysis must specify avalanche model.



## Ex 5. Change Mobility Models

Projects: /PostBasic/question/sdevice/nmos

- Copy nmos project to a new project named as nmos\_mobility.
- Edit nmos\_mobility project's Physics section as follows:

#-Mobility( DopingDependence HighFieldSaturation Enormal)
Mobility( HighFieldsaturation Enormal)

 Run nmos\_mobility project, and compare its Id-Vg curve with nmos project's.



# **Examples of Analysis**

- Mixed-Mode Transient Analysis
- AC Analysis





### **Transient and AC Analyses**

- The transient analysis is usually done by using the mixed-mode simulation.
- Under the following conditions, the transient analysis can be done without the mixed-mode simulation.
   There is only a physical device;
   The piecewise linear source is used.
- The AC analysis must to use the mixed-mode simulation.
- The C-V characteristics can be obtained by the AC analysis.



### **Mixed-Mode Simulation**



- SDevice is a single-device simulator, and a mixed-mode device and circuit simulator.
- Provides a number of compact models for use in mixed-mode simulations.
   >SPICE, HSPICE, built-in models, etc.



### **Input Command File of Mixed-Mode**

Three levels of device definition
 Global
 Device
 Instance

 Mixed-Mode simulation need to specify two new sections:
 >Device section



✓ Device section defines physical devices used in the sys
 ≻System section

 System section defines the netlist of physical devices ar circuit elements to be solved.



### **Example: CMOS Inverter Transient Analysis**

Project: /PostBasic/example/sdevice/cmos\_inverter\_transient Description: Simulate the transient characteristics.



• CMOS inverter consists of both NMOS and PMOS devices.



# **Device Section (1/2)**

```
Device NMOS {
                                         Device PMOS{
 Electrode{
                                           Electrode{
    { Name="source"
                     Voltage=0.0 }
                                             { Name="source"
                                                             Voltage=0.0 }
    { Name="drain"
                     Voltage=0.0 }
                                             { Name="drain"
                                                              Voltage=0.0 }
   { Name="gate" Voltage=0.0 }
                                             { Name="gate" Voltage=0.0 }
   { Name="substrate" Voltage=0.0 }
                                             { Name="substrate" Voltage=0.0 }
                                           }
  }
 File{
                                           File{
    Grid
            = "@tdr|nmos@"
                                             Grid
                                                         = "@tdr|pmos@"
    Plot
                = "@tdrdat@"
                                             Plot
                                                         = "@tdrdat@"
                = "@plot@"
    Current
                                             Current
                                                         = "@plot@"
                = "@parameter@"
                                              Parameter
                                                         = "@parameter@"
    Parameter
  }
                                           }
 Physics{
                                           Physics{
AreaFactor=5
                                         AreaFactor=10
Mobility( DopingDep HighFieldSaturation
                                         Mobility( DopingDep HighFieldSaturation
Enormal)
                                         Enormal)
EffectiveIntrinsicDensity(oldSlotboom)
                                         EffectiveIntrinsicDensity(oldSlotboom )
  }
                                           }
}
                                         }
```



## **Device Section (2/2)**

- Each Device section contains an Electrode, a File, and a Physics section.
- In mixed mode, currents from different devices interact need to be scaled according to the actual device widths. The AreaFactor specifications in the Physics section are used to define the width of the devices.



# System Section (1/5)

```
System{
 Vsource_pset vdd (dd 0) { dc = 0.0 }
 Vsource_pset vin (in 0) { pulse = (0.0)
                                             # dc
                                   1.5 # amplitude
                                   10e-12 # td
                                   10e-12  # tr
                                   10e-12 # tf
                                   60e-12 # ton
                                   140e-12)  # period
 }
 NMOS nmos1 ( "source"=0 "drain"=out "gate"=in "substrate"=0 )
 PMOS pmos1 ( "source"=dd "drain"=out "gate"=in "substrate"=dd )
 Capacitor_pset cout ( out 0 ){ capacitance = 3e-14 }
 Plot "n@node@_sys_des.plt" (time() v(in) v(out)
                           i(nmos1.out) i(pmos1.out)
i(cout.out))
}
```

• The node 0 is predefined as the ground node.



## System Section (2/5)

- The keyword Vsource\_pset represents a compact model voltage source.
- The keyword Capacitor\_pset represents a compact model capacitor.
- NMOS and PMOS, defined in the previous Device sections are used here to define the two circuit elements, nmos1 and pmos1, respectively.
- The Electrode block of the Device section are all connected to a node of the circuit. For example, "source"=0, "drain"=out.



## System Section (3/5)





# System Section (4/5)

• vin is defined as a time-dependent voltage source that generates a pulse train. Available time-dependent sources are as follows:

pulse	Pulse description	
sine	Sinusoidal source description	
sin <sup>a</sup>	Sinusoidal source description	
exp	Exponential source description	
pwl	Piecewise linear description	
sffm	Single-frequency FM description	

- a. Equivalent to the sine parameter.
- Refer to the following manual for more information.
   Compact Models User Guide (cm\_ug.pdf)


# System Section (5/5)

System{

}

```
...
Plot "n@node@_sys_des.plt" ( time() v(in) v(out)
i(nmos1,out) i(pmos1,out)
i(cout,out) )
```

- The Plot statement inside the System section allows voltages and currents at selected nodes of the circuit to be recorded.
- To record voltage, specify the node name. For example, v(in), v(out).
- To record current, specify both the element and the node name through which the current flows. For example, i(nmos1,out), i(pmos1,out).



# **Global File and Plot Sections**

Global File section
File{
 Output = "@log@"
}

- Global Plot section
  Plot{
   eDensity
   hDensity
   ...
  }
- Used by all Device sections.
- The global File (Plot) section can be placed either inside a Device definition.



# Solve Section (1/2)

```
Solve{
 NewCurrentFile="init"
 Coupled(Iterations=100){ Poisson }
 Coupled{ Poisson Electron Hole Contact Circuit }
 Quasistationary(
    InitialStep=1e-3 Increment=1.35
    MinStep=1e-5 MaxStep=0.05
    Goal{ Parameter=vdd.dc Voltage= 1.5 }
 ){ Coupled{ nmos1.poisson nmos1.electron
                                              nmos1.contact
             pmos1.poisson pmos1.hole
                                              pmos1.contact
             circuit }
  }
 NewCurrentFile=""
 Transient (
    InitialTime=0 FinalTime=200e-12
    InitialStep=1e-12 MaxStep=5e-12 MinStep=1e-15
 ){ Coupled{ nmos1.poisson nmos1.electron nmos1.contact
                    pmos1.poisson pmos1.hole
pmos1.contact
                    circuit }
  }
```



# Solve Section (2/2)

#### **Transient Analysis Syntax:**



- InitialTime (0s by default) is start time; FinalTime is final time.
- InitialStep controls the size of the first step of the ramping (0.1s by default). MaxStep (1s by default) and MinStep (0.001s by default) limit this change.



# **Output Files of Mixed-Mode**







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## **CMOS Transient Characteristic**





## **Example: NMOS Small-Signal AC Analysis**



# **Device Section**

```
Device NMOS{
  Electrode {
    { name="source" Voltage=0.0 }
    { name="drain" Voltage=0.0 }
{ name="gate" Voltage=0.0 }
    { name="substrate" Voltage=0.0 }
  }
  File{
                = "@tdr@"
     Grid
     Plot
                   = "@tdrdat@"
     Current = "@plot@"
                = "@parameter@"
     Param
  }
  Physics{
    Mobility( DopingDep HighFieldSaturation Enormal )
    EffectiveIntrinsicDensity( oldSlotboom )
  }
```

 The AC analysis needs to be done by the mixed-mode simulation. One or more Device sections are required to define the physical device(s).



# **Global File Section**



- The file name for the AC analysis output (n2\_ac\_des.plt), is declared in the global File section.
- It contains the components of the conductance matrix A and the capacitance matrix C.  $Y = A + j\omega C$ , where  $\omega = 2\pi f$ .



Family Tree

SeniaurusD

dessis

[n2]: --

SeniourusSE

devise

[n1]: --

frequency

V(d) V(s)

V(g) V(b) a(d,d) c(d,d)

a(d,s) c(d,s)

la(d,g)

c(d,g) a(d,b)

|c(d,b)|

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# **System Section**



• For small-signal analysis simulations, an attached voltage source is required for each terminal if the terminal is to be included in the AC analysis.



# Solve Section (1/3)

```
Solve{
 NewCurrentFile="init"
 Coupled(Iterations=100){ Poisson }
 Coupled{ Poisson Electron Hole }
 Quasistationary (
    InitialStep=0.1 Increment=1.3
    MaxStep=0.5 Minstep=1.e-5
    Goal { Parameter=vg.dc Voltage=-3}
 ){ Coupled { Poisson Electron Hole } }
 #-ramp gate
 NewCurrentFile=""
 Quasistationary (
    InitialStep=0.01 Increment=1.3
    MaxStep=0.05 Minstep=1.e-5
    Goal { Parameter=vg.dc Voltage=3}
 ) ACCoupled (
      StartFrequency=1e6 EndFrequency=1e6 NumberOfPoints=1
      Decade
      Node(d s q b) Exclude(vd vs vq vb)
      ACCompute (Time = (Range = (0 \ 1) Intervals = 20))
    ) { Poisson Electron Hole }
```



# Solve Section (2/3)

- The initial Quasistationary block biases the device to the starting gate voltage for the CV sweep.
- The keyword ACCoupled activates the small-signal analysis during the next Quasistationary sweep. In this example, the AC analysis is performed at a single frequency (1 MHz) only.

#### AC Analysis Syntax:





# Solve Section (3/3)

- The AC analysis is performed in a mixed-mode environment.
- The AC analysis computes the complex admittance Y matrix.
- The options StartFrequency, EndFrequency, NumberOfPoints, and Decade (or Linear) are used to select the frequencies at which the analysis is performed and the frequency distribution.
- A Node list must be given, which nodes are to be included in the Y-matrix calculation. With it, for each frequency, the compact equivalent small signal model is generated between the given nodes.
- The Exclude list is used to remove a set of circuit or physical devices from the AC analysis.
- The (optional) ACCompute statement enforces that the AC analysis is performed on a set of predefined bias points.



## **NMOS C-V Characteristic**



Predictable Success



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# Ex 6. Observe Transient and AC's Results

Observe the following projects' results.

 *PostBasic/example/sdevice/cmos\_inverter\_transient*

time v(in) v(out) i(nmos1,out) i(pmos1,out) i(cout,out)



#### /PostBasic/example/sdevice/ac







## **Quasistationary, Transient and AC Analysis**

	Quasistationary	Transient	AC (Y-parameters)
Input Signals	DC	Time-dependent sources	Small-signal AC sources
Simulation Domain		Time	Frequency
Need Quasistationary Analysis?		Yes	Yes
Mixed-Mode Necessary?	No	No	Yes
"t" Variable	"t" is the internal variable. (0->1)	"t " is the real time [s].	
Applications	DC operating point ,DC sweep	Transient response	C-V, FT



### Inspect





## Outline

- GUI interactive mode
  - Load curve file, plot curves
  - Edit Plot area, Axes
  - Create new curve
  - Formula library refer to manual 2007.12 P.25,48
  - Macros refer to manual 2007.12 P.26,50
  - Save, Export
- Script file batch mode
  - Record each operation step on interactive mode to generate a script file.
  - Script a command file refer to example 0.18um nMOS
  - Extract standard parameters of the extraction library



#### **Inspect Script Basic**

Version A-2008.09 Rev0.0





## Agenda

- Basic Operations and Script Commands
  - Load plt File: proj\_load
  - Create Curve : cv\_createDS
  - Set Attributes: gr\_setAxisAttr; cv\_setCurveAttr
  - Extract Variables : cv\_compute; ft\_scalar
- Mathematical Formulas and Macros
  - Mathematical Formulas
  - ➤ Macros
- Threshold Voltage Extraction
  - Definitions of Threshold Voltage
  - Inspect Script



## **Inspect Script**

- Inspect can be controlled by using a simple scrip language. For example, a script can load a project (data file), draw curves, and perform mathematical computations on curves.
- A script can be written manually or created automatically by recording actions performed interactively through the graphical user interface.
- Inspect script can extract variables to SWB family table.

	Family Tree				Variable Values			
	SentaurusP		SenkurusSE	SeniaurusD	Inspect			
	sprocess		sde	ld∨g	rolloff			
		Lgshift				Lg	vt	vt1
1		0.0				0.065	0.316	0.183
2		0.005				0.075	0.340	0.215
3		0.01				0.085	0.327	0.206
4		0.0175				0.100	0.315	0.199
5		0.0325				0.130	0.298	0.188
6		0.0925				0.250	0.257	0.158



## **Basic Operations and Script Commands**





## **Basic Operations and Script Commands**

- The basic operations and script commands are explained:
  - Load plt File: proj\_load
  - > Create Curves : cv\_createDS
  - Set Attributes: gr\_setAxisAttr; cv\_setCurveAttr
  - Extract Variables : cv\_compute; ft\_scalar
- A backslash '\' is used to extend a command to multiple

lines if it appears as the last character on the line.



## Load plt File ~ Operation ~ (1/3)

S Inspect@okukinu vA-2008.09				
<u>File</u> <u>E</u> dit <u>C</u> urve <u>S</u> cript Extensions <u>H</u> elp				
Load Dataset				
Update Datasets				
Automatically Update Datasets	ill and Datasat "			
Delete Datasets	Load Dataset			
Load Setup	-			
<u>S</u> ave Setup	-			
	-			
Restore All	0.8 —			
Sa <u>v</u> e All				
<u>E</u> xport >	-			
Write EPS	-			
Write PS	-			
Print Ctrl+P	0.6 —			
	_			
Preferences				
Exit Ctrl+Q				
	1			
	0.4 -			



## Load plt File ~ Operation ~ (2/3)

S Inspect@okukinu vA-2008.09		
<u>F</u> ile <u>E</u> dit <u>C</u> urve <u>S</u> cript E <u>x</u> tensions <u>H</u> elp		
🖻 🚑 💠 🛛 🕿 🛄 🔍 🍳 🔍 江 💘  🧱		
Datasets Curves	a       a	
	0.6       File names: n2_des.plt       Open         Files of type:       XY plot files (*.plt)       Cancel         2. Set "Files of type"       4. Click "O	pen"



## Load plt File ~ Operation ~ (3/3)





## Load plt File ~ Command ~

• Load plt file

n2\_des.plt : the name of the file to load.

n2\_des : the arbitrary name user can define for this dataset.



## Create Curve ~ Operation ~ (1/4)





## Create Curve ~ Operation ~ (2/4)

Inspect@okukinu vA-2008.09
<u>Eile E</u> dit <u>C</u> urve <u>S</u> cript E <u>x</u> tensions <u>H</u> elp
≱⊕ ◊ [≈] 💭 � � X [] ♥ [] 🔚 🐘 🦠 🦉 🐴   → 💼 [] 🕺 🖞
-Datasets
n2_des
drain 0.6 - source -
OuterVoltage QuasiFermiPotential DisplacementCurren eCurrent TotalCurrent Charge 0.2
New
To X-Axis 4 Edit Click "To X-Axis"
To Left Y-Axis Delete
To Right Y-Axis Delete All 0 0.2
in data selected for X-Axis



## Create Curve ~ Operation ~ (3/4)

<mark>S</mark> Inspect@okukinu vA-200	8.09					
<u>File Edit Curve Scrip</u>	t E <u>×</u> tensions <u>H</u> elp					
🚅 🚑 ¢ [ 🕿 [ 💭 [ 🔍	م 🗶 🖸 🏹 🔳	🐂 🗞	🍋 🌇 🗍	▶ <u> </u>	Y Y2	
-Datasets	- Curves	1				
n2_des						
		0.8 -				
		0.0				
time						
gate						
substrate drain	5 Sold		"~~	nta	ct"	
source	J. Jei			ліа		
OuterVoltage						
InnerVoltage		0.4				
QuasiFermiPotential						
eCurrent		1				
hCurrent	6 Sale		"To	tal	LIRRO	m#"
Charge	0. 3616			nan	June	;  L
	, []	0.2 -				
	New	1				
To X-Axis	Edit	1				
	7 Clie	L . 6	Ta		VA.	
To Left Y-Axis		<b>K</b> 1	10	Len	I-A	KIS
To Pight V. Avia	Doloto All	0+	1	1 1	0.2	
Selected est for V Avis - n2	dec.gotoOuter/(elfoge					



## Create Curve ~ Operation ~ (4/4)





# **Create Curve ~ Command ~**



- TotalCurrent\_Drain : a unique name for the new curve.
- {n2\_des gate OuterVoltage} : a list of data to use for the x-dataset.
- {n2\_des drain TotalCurrent} : a list of data to use for the y-dataset.
- y : optional parameter specifying the axis to use; the default is y; the options are y or y2.



## **Set Attributes**

• This section describes the functions that change the attributes of the axes, curves, and legend.



## Set the Axis Attributes ~ Operation : Start ~

S Inspect@okukinu vA-20	008.09			
<u>Eile Edit C</u> urve <u>S</u> cript E <u>x</u> tensions <u>H</u> elp				
🖻 🚑 o [ 🐴 [ 💭 [ 🍳	l 🔍 🔍 [] 🔍 🔳 🏢			
Datasets	Curves			
n2_des	TotalCurrent_drain	8e-05 -		
time gate substrate drain source		6e-05-		
OuterVoltage InnerVoltage QuasiFermiPotential DisplacementCurren		4e-05-		
eCurrent hCurrent TotalCurrent Charge	New	2e-05 -		
To X-Axis	Edit	<b>1. Double-click the axis</b>		
To Left Y-Axis	Delete			
To Right Y-Axis	Delete All	<sup>3</sup> . Δ		
🍂 Start 🛛 🥶 💽 🚱 🚺	🤇 🔽 🕼 🔯 🖉 🖉	🧉 これがら販売予定   📴 8 Windows Expl 🗸 🕟 Inbox - Microsoft   🗽 4 X Server for 🗸 76 2 Microsoft Offic 🗸 🦉 Inspect007.bmp   😰 🌒 A 🛛 « 🔍 糾 🏨 17:19		



## Set the Axis Attributes ~ Operation : Editing Title (1/2) ~





## Set the Axis Attributes ~ Operation : Editing Title (2/2) ~




# Set the Axis Attributes ~ Operation : Editing Scale~





### Set the Axis Attributes ~ Operation : Editing Pattern





### Set the Axis Attributes ~ Operation : Editing Pattern





### Set the Axis Attributes ~ Command ~

gr\_setAxisAttr <u>X</u> {<u>Vg [V]</u>} {arial 15} <u>0 8</u> <u>black 1</u> \ \ **1. 3. 5. 8. 11. 13.** {arial 15} 0 5 0 black

- X : a keyword (X, Y, or Y2) specifying an axis.
- Vg [V] : the axis title.
- {arial 15} : the font size of the axis title.
- 08: minimal and maximal values of the axis.
- black : the color of the axis.
- 1: the width of the axis line.



### Set the Axis Attributes ~ Operation : Editing Ticks (1/2)





### Set the Axis Attributes ~ Operation : Editing Ticks (2/2)





### Set the Axis Attributes ~ Operation : Changing Log/Lin





### Set the Axis Attributes ~ Operation : Editing Font of







# Set the Axis Attributes ~ Command ~

```
gr_setAxisAttr <u>X</u> {Vg [V]} {arial 15} 0 8 black 1 \
\
<u>{arial 15} 0 5 0 black</u>
16. 18. 19.20. 23.
```

- X : a keyword (X, Y, or Y2) specifying an axis
- {arial 15} :the font size of the tick label
- 0 : the angle at which the tick labels are drawn
- 5: the number of secondary ticks between the main ticks
- black : the color of the axis title



# Set Curve Drawing Attributes ~ Operation : Start ~





### Set Curve Drawing Attributes ~ Operation : Editing General Part





### Set Curve Drawing Attributes ~ Operation : Editing Line Part (1/2)~





# Set Curve Drawing Attributes ~Operation : Editing Line Part (2/2)~





### Set Curve Drawing Attributes ~ Operation : Editing Marker (1/4)





 $\sim$ 

### Set Curve Drawing Attributes ~ Operation : Editing Marker (2/4)





 $\sim$ 

# Set Curve Drawing Attributes ~ Operation : Editing Marker (3/4)~

	 8e-05	
	-	Curve Attribute
		General Line Marker Interpolation
	-	Shape: square 👻
	6e-05 — -	Size: 5
	-	Outline Color:
€	-	
rrent	-	<sup>outline Width: 11</sup> <b>12. Change "Outline Width"</b>
alCu	4e-05 -	Fill Color:
Ę	-	
	-	
	-	QK Apply Cancel
	2e-05 -	
	-	
	-	
	- 0	



# Set Curve Drawing Attributes ~ Operation : Editing Marker (4/4) ~

	- 8e-05 -	
	-	Curve Attribute
	-	General Line Marker Interpolation
	- 6e-05 - - -	Shape: square
		Size: 5
ent (A		
TotalCurre	4e-05 - - -	Fill Color:
	-	
	2e-05 -	•
	-	
	0 -   0	0.5
		(V) anothervature



# Set Curve Drawing Attributes ~ Command ~

```
cv_setCurveAttr TotalCurrent_Drain IdVg black solid 3 \\ 3. 5. 6. 7.
square 5 black 1 black
9. 10. 11. 12. 13.
```

- TotalCurrent\_Drain: the curve name.
- IdVg : the curve legend.
- black : the color of the curve line.
- solid: the drawing style of the curve line.
- 3: the width of the curve line.
- square : a keyword for the marker shape.
- 5: the marker size.
- black : the color of the marker outline.
- 1 : the width of the marker outline.
- black : the fill-in color of the marker.



# **Compute a Scalar Using the Formula**

 The formula library allows some basic calculations to be performed on one or more selected curves.

cv\_compute "formula" xmin xmax ymin ymax

- $\succ$  formula : the string with the formula to evaluate.
- > xmin, xmax, ymin, ymax : the range for which the formula is applied.



# **Extract Variables**

- The Inspect command ft\_scalar prints the extracted value and passes it to Sentaurus Workbench.
- Examples:

```
set maxid [cv_compute "vecmax(<Id>)" 0 0.5 0 1.0]
ft_scalar id_max $maxid
```

set vt [cv\_compute "vecvalx(<Id>, 1e-5)" 0 1.0 0 1.0]
ft\_scalar Vt \$vt



# **Extraction Library**

 The commands provided by this library are used to extract various parameters from I–V curves. The library is loaded with the command:

load\_library EXTRACT

• Refer to Inspect manual for more information.



# **RF Extraction Library**

 The commands provided in this library are used to extract RF parameters from small-signal data. The library is loaded with the command:

load\_library RFX

• Refer to Inspect manual for more information.



# **Recording Script**

- A script can be created automatically by recording actions performed interactively through the graphical user interface.
- To create a script:
  - A Script Name dialog box is displayed, which prompts you to select or create a script file.

#### Script > Record > Start

After selecting the file name, Inspect starts to store every operation until recording is stopped.

 Script > Record > Stop





# **Inspect Execution Mode**

Inspect has two execution modes: interactive and batch mode. You can change mode by:

#### **Right button>Edit Input>Preferences...**







#### **Mathematical Formulas and Macros**





# Mathematical Formulas (1/2)

- Click the New button below the Curves area in the Inspect main window.
- The **Create Curve** dialog box is displayed. The right pane lists available formula commands (mathematical functions).

Create Curve		×
Curves TotalCurrent_drain	Name:Curve_1 Formute:vecmin( <totalcurrent_drain>) Map Curve To ◆ Left Y-Axis ◇ Right Y-Axis</totalcurrent_drain>	
Macros ADD VT VT1 gm Rout Ron IDSS test1 test12	available formula commands are: acos, acosh, asin, asinh, atan, atanh, cbrt, ceil, cos, cosh, erf, erfc, exp, fabs, floor, gamma, j0, j1, Igamma, log, log10, pow, sin, sinh, sqrt, tan, tanh, y0, y1, diff, integr vecmax, vecmin, vecvalx, vecvaly, tangent, veczero Curve names in the formula must be surrounded by "<" and ">". If you are using macros, CURVE must be replaced with the curve name and N with a scalar value.	
	QK Apply Cancel	



# Mathematical Formulas (2/2)

- vecmax (curve) • Maximum y-value. vecma vecmin (curve) • Minimum y-value. vecvalx (curve, scalar)  $\succ$  x-value at a given y vecvaly (curve, scalar) ٠ y-value at a given x veczero (curve) veczero  $\succ$  x-value at y = 0. diff (curve) ٠ Returns the first derivative of the curve. vecmin integr (curve) •
  - ➢ Returns the integral of the curve.
- tangent (curve)
  - Returns the tangent.



# Macros (1/3)

 Macros are predefined commands that can be later recalled. For example, in Inspect, there is a predefined macro, VT, which performs the threshold voltage extraction.





# **Macros (2/3)**

#### Macro usage:



Predictable Success

# **Macros (3/3)**

Macro definition can be edited by

#### **Edit>Define Macros...**

	Macro Editor
Macro List	Name: VT
VT VT1 1 Select "VT"	Macro: vecvalx(tangent( <c 1="">,veczero(diff(<c 1="">) - vecmax(diff(<c 1="">)</c></c></c>
Rout	<b>2. Macro definition</b> available formula commands to create macros are:
test1 test2	acos, acosh, asin, asinh, atan, atanh, cbrt, ceil, cos, cosh, erf, erfc, exp, fabs, floor, gamma, j0, j1, Igamma, log, log10, pow, sin, sinh, sqrt, tan, tanh, y0, y1, diff, integr
Add / Edit	vecmax, vecmin, vecvalx, vecvaly, tangent, veczero
Delete	Use " <c n="">" as place holders for curves and "<s n="">" for scalar values in the macros, where n represents the argument used in the macro (n must start with 1).</s></c>
	Close



# **Threshold Voltage Extraction**





# **Definitions of Threshold Voltage (1/2)**





# **Definitions of Threshold Voltage (2/2)**

Macros
 VT:

vecvalx(tangent(<c1>, veczero(diff(<c1> - vecmax(diff(<c1>)))), 0.0)

VT1:

vecvalx(<c1>, 1.0e-7)

• Script functions **VT**:

f\_VT curveName xmin xmax ymin ymax

#### VT1:

f\_VT1 curveName xmin xmax ymin ymax

xmin, xmax, ymin, ymax, the range for computing the result; default values correspond to the full curve range.



# Inspect Script (1/4)

```
N @node@
set
    Vd
           0.05
set
set Lgshift @Lgshift@
set Lg [expr 2.0*$Lgshift+0.065]
ft_scalar Lg [format %0.3f $Lg]
proj_load @plot@ PLT($N)
cv_createDS IdVg($N) \
 "PLT($N) gate OuterVoltage" "PLT($N) drain TotalCurrent" y
cv_setCurveAttr IdVg($N) "Id" red solid 2 circle 0 defcolor 1 defcolor
gr_setAxisAttr X {Gate Voltage (V)} 12 {} {} black 1 10 0 5 0
gr_setAxisAttr Y {Drain Current (A/um)} 12 {} {} black 1 10 0 5 0
gr_setTitleAttr "Id vs. Vqs (Lq=$Lq um, Vds=$Vd V)" 14 center
#- Extraction
#- Calculate the threshold voltage [V]
set vt [f_VT IdVa($N)]
ft_scalar vt [format %0.3f $vt]
set vt1 [f_VT1 IdVq($N)]
ft_scalar vt1 [format %0.3f $vt1]
```



# Inspect Script (2/4)

#### Set variables:

set	Ν	@node@
set	Vd	0.05
set	Lgshift	@Lgshift@
set	Lg	[expr 2.0*\$Lgshift+0.065]





# Inspect Script (3/4)

Load plot file:

proj\_load @plot@ PLT(\$N)

Create curve:

cv\_createDS IdVg(\$N) \
 "PLT(\$N) gate OuterVoltage" "PLT(\$N) drain TotalCurrent" y

#### Set curve attribution:

cv\_setCurveAttr IdVg(\$N) "Id" red solid 2 circle 0 defcolor 1 defcolor

#### Set axis attributions:

gr\_setAxisAttr X {Gate Voltage (V)} 12 {} {} black 1 10 0 5 0 gr\_setAxisAttr Y {Drain Current (A/um)} 12 {} {} black 1 10 0 5 0

Set title:

gr\_setTitleAttr "Id vs. Vgs (Lg=\$Lg um, Vds=\$Vd V)" 14 center


# Inspect Script (4/4)

Calculate VT:				Export the variable to the Family				
set	vt	[f_VT	IdVg(\$N)]	Table of Ser	ntauru	is Workb	ench:	
Calcu	late V	T1:		ft_scalar	Lg	[format	%0.3f	\$Lg]
set	vt1	[f_VT	1 IdVg(\$N)]	ft_scalar ft_scalar	vt vt1	[format [format	%0.3f %0.3f	\$vt] \$vt1]

	Family Tree					Variable Values			
	SentaurusP		SenkurusSE	SentaurusD	Inspect				
	spro	cess	sde	ld∨g	rolloff				
		Lgshift				Lg	vt	vt1	
1		0.0				0.065	0.316	0.183	
2		0.005				0.075	0.340	0.215	
3		0.01				0.085	0.327	0.206	
4		0.0175				0.100	0.315	0.199	
5		0.0325				0.130	0.298	0.188	
6		0.0925				0.250	0.257	0.158	



#### 90nm nMOS Exercise





## Preparation

- Copy the 0.18um\_nMOS project and rename it as 90nm\_nMOS, then clear up all the output files
- SProcess uses the –f option to speed up the simulation time for structure verification
  - -f option skip diffusion and monte carlo implant step
  - Refer to SProcess manual 2007.12 P.52
  - It will cause some parameter extraction failure because of a missing net doping profile. When we are sure the device structure is correct, we should remove the –f option to do a complete simulation.



# **Structure Comparison**



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# **Process Comparison**

#### • 0.18um nMOS

Well/Vth implant & anneal Boron dose=2e13 energy=200 tilt=0 rot=0 Boron dose=1e13 energy=80 tilt=0 rot=0 Boron dose=6e12 energy=25 tilt=0 rot=0 diffuse temp=1050 time=0.3<s>

#### Gox~33A

diffuse temp=650 ramprate=0.6666 time=5 diffuse temp=850 time=10 O2 1atm diffuse temp=850 ramprate=-0.6666 time=5

POLY height = 0.18um deposit poly type=isotropic thickness=0.18

Halo/LDD implant & anneal Boron dose=1e13 energy=15 tilt=30 / rot=0,90,180,270 Arsenic dose=1e15 energy=20 tilt=0 rot=0 diffuse temp=1050 time=0.02<s>

#### • 90nm nMOS

Well/Vth implant & anneal Boron dose=2e13 energy=200 tilt=0 rot=0 Boron dose=1e13 energy=80 tilt=0 rot=0 Boron dose=8e12 energy=30 tilt=0 rot=0 diffuse temp=1050 time=0.3<s>

#### Gox~18A

diffuse temp=650 ramprate=0.6666 time=5 diffuse temp=850 time=10 O2=0.8<l/min> N2=9.2<l/min> 1atm diffuse temp=850 ramprate=-0.6666 time=5

POLY height = 0.15um deposit poly type=isotropic thickness=0.15

Halo/LDD implant & anneal Boron dose=2e13 energy=12 tilt=30 / rot=0,90,180,270 Arsenic dose=1e15 energy=5 tilt=0 rot=0 diffuse temp=1020 time=0.03<s>



# **Process Comparison**

#### • 0.18um nMOS

#### Nitride Spacer

deposit nitride type=isotropic thickness=0.06 etch nitride type=anisotropic thickness=0.084 etch oxide type=anisotropic thickness=0.01

#### • 90nm nMOS

#### **ONO** Spacer

Source/Drain implant & anneal implant Arsenic dose=4e15 energy=30 tilt=0 rot=0 diffuse temp=1080 time=0.02<s>

Source/Drain implant & anneal implant Phosphorus dose=1e15 energy=6 tilt=0 rot=0 implant Arsenic dose=5e15 energy=30 tilt=0 rot=0 diffuse temp=1050 time=0.03<s>



## **SProcess Mesh Comparison**



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## **SDevice Mesh Comparison**



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# Id\_Vg Curve Comparison

• 0.18um nMOS

• 90nm nMOS

Vdd=1.5v; Vds=0.05v





## Hints

- Need to translate the process conditions into correct syntax of Sprocess.
- Poly height has been changed from 0.18um to 0.15um, need to update the coordinate of gate contact in Sprocess.
- After finish the modification of Sprocess, whole simulation flow (Sprocess, SSE, Sdevcie, Inspect) can be executed well.
- In Sprocess, fine tune LDD & SD refine-box to get a more accurate doping profile.
- In SSE, fine tune variable "PNres" to optimize the mesh of LDD and SD junction to get a more accurate Sdevice simulation result.



# C-V Device Simulation Breakdown Device Simulation pMOS Simulation





# **CV-curve: long channel transistor**





# **C-V Device Simulation**

- Small-signal AC analysis (2007.12 P.183)
  - AC simulation are performed in mixed mode (2007.12 P.163).



 Extract conductance and capacitance of each node, and output matrix A (conductance) and matrix C (capacitance).

• j = Yu = Au + iωCu

- j is the vector containing the small-signal currents at all nodes.
- u is the corresponding voltage vector.



# **C-V Simulation Command File**

```
Device "device1"
     File
                    { "define device input and output file" }
                    { "same with IV simulation" }
     Electrode
     Physics
                    { "same with IV simulation and turn on minority carrier quantum"
       potential equation for accumulation side CV extraction" }
                    { "define system output file" }
File
                    { "same with IV simulation" }
Plot
Math
                    { "same with IV simulation" }
System { "based on previous device1 and the voltage source of each node
  construct a simple circuit" }
```

Solve { "set bias sweeps sequence, solve transport models and extract AC parameters" }



# **C-V Device Simulation Result**



## **Breakdown Device Simulation**

- n-th step converge, next  $\Delta V_{n+1} > \Delta V_n$
- n+1-th step diverge, then  $\Delta V_{n+1} = \Delta V_n/2$
- The voltage step will be divided by 2 again and again, until it converges or until it reaches a minimum step that we define in the command file.





# **Breakdown Device Simulation**

- An approach to solve divergent and snapback issues
  - Introduction please refer to on-line training material "SDevice section D.1 MOSFET Breakdown Simulation "



# **Breakdown Device Simulation**

- Modify SDevice command file
  - Turn on Avalanche and Band2Band model
  - Solve dual carrier transport
  - Detail please refer to 90nm nMOS breakdown example.



# Modify nMOS Template to pMOS

- SProcess: change to pMOS process condition
- SDE: change PLOY dopant type from N-type to P-type
- SDevice
  - Change majority carrier from electron to hole and related models. (Exchange e and h in input file in most cases.)
  - Change bias condition
- Inspect: change device type and extraction region for "Extraction library"
- Detail please refer to 90nm pMOS example



#### **SolvNet Introduction**





# Outline

- How to register a SolvNet account
- What kind of TCAD resources we can find on SolvNet
  - Software, Manual, Release Notes, TCAD Example updates
- Two advanced TCAD examples of the SolvNet example library
  - 2D Strained Silicon 45nm CMOS Reference Flow Demo
  - 3D nMOSFET Demo



#### SolvNet Website http://solvnet.synopsys.com/

File       Edit       View       Favorites       Tools       Help	Links						
	Links						
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